GL868 DUAL Hardware User Guide

1vv0300896 Rev. 5 – 2012-06-06

Making machines talk.

APPLICABILITY TABLE

PRODUCT
GL868-DUAL
GL868-DUAL DATA ONLY

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Contents

1. INTRODUCTION 7
1.1. SCOPE 7
1.2. AUDIENCE 7
1.3. CONTACT INFORMATION, SUPPORT 7
1.4. DOCUMENT ORGANIZATION 7
1.5. TEXT CONVENTIONS 8
1.6. RELATED DOCUMENTS 9
2. OVERVIEW 10
3. GL868 MECHANICAL DIMENSIONS 11
4. GL868 MODULE CONNECTIONS 12
4.1. PIN-OUT 12
4.2. PIN LAYOUT 15
5. HARDWARE COMMANDS 16
5.1. AUTO-TURNING ON THE GL868 16
5.2. TURNING OFF THE GL868 18
5.3. RESETTING THE GL868 20
5.3.1. Hardware Unconditional restart 20
6. POWER SUPPLY 22
6.1. POWER SUPPLY REQUIREMENTS 22
6.2. POWER CONSUMPTION 23
6.2.1. Power consumption Plots 24
6.3. GENERAL DESIGN RULES 28
6.3.1. Electrical Design Guidelines 28
6.3.2. Thermal Design Guidelines 32
6.3.3. Power Supply PCB layout Guidelines 33
7. ANTENNA 34
7.1. GSM ANTENNA REQUIREMENTS 34
7.2. GSM ANTENNA - PCB LINE GUIDELINES 35
7.3. GSM ANTENNA - INSTALLATION GUIDELINES 35
8. LOGIC LEVEL SPECIFICATIONS 36
8.1. RESET SIGNAL 37
9. SERIAL PORTS 38
9.1. MODEM SERIAL PORT 38
9.2. RS232 LEVEL TRANSLATION 39
9.3. 5V UART LEVEL TRANSLATION 43
10. AUDIO SECTION OVERVIEW (NOT AVAILABLE ON GL868-DUAL DATA ONLY VERSION) 45
10.1. ELECTRICAL CHARACTERISTICS 48

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10.1.1. Input Lines *48*
10.1.2. Output Lines *49*

11. GENERAL PURPOSE I/O **50**

11.1. GPIO Logic levels 51
11.2. Using a GPIO Pad as INPUT 52
11.3. Using a GPIO Pad as OUTPUT 52
11.4. Using the RFTXMON Output GPIO5 52
11.5. Using the Alarm Output GPIO6 53
11.6. Using the Buzzer Output GPIO7 53
11.7. Magnetic Buzzer Concepts 54
11.7.1. Short Description *54*
11.7.2. Frequency Behavior *54*
11.7.3. Power Supply Influence *55*
11.7.4. Working Current Influence *55*
11.8. STAT LED Indication of network service availability 56
11.9. SIMIN detect function 57
11.10. RTC Bypass out 58
11.11. SIM Holder Implementation 58

12. DAC AND ADC SECTION **59**

12.1. DAC Converter 59
12.1.1. Description *59*
12.1.2. Enabling DAC *60*
12.1.3. Low Pass Filter Example *60*
12.2. ADC Converter 61
12.2.1. Description *61*
12.2.2. Using ADC Converter *61*
12.3. Debug of the GL868 in production 61

13. MOUNTING THE GL868 ON YOUR BOARD **63**

13.1. General 63
13.2. Module finishing & dimensions 63
13.3. Recommended foot print for the application 64
13.4. Stencil 65
13.5. PCB pad design 65
13.6. Recommendations for PCB pad dimensions (mm) 65
13.7. Solder paste 66
13.7.1. GL868 Solder reflow *67*

14. PACKING SYSTEM **68**

14.1. Moisture sensibility 69

15. CONFORMITY ASSESSMENT ISSUES **70**

16. SAFETY RECOMMANDATIONS **71**

17. DOCUMENT HISTORY **72**

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1. Introduction

1.1. Scope

The aim of this document is the description of some hardware solutions useful for developing a product with the Telit GL868 module.

1.2. Audience

This document is intended for Telit customers, who are integrators, about to implement their applications using our GL868 modules.

1.3. Contact Information, Support

For general contact, technical support, to report documentation errors and to order manuals, contact Telit's Technical Support Center (TTSC) at:

TS-EMEA@telit.com
TS-NORTHAMERICA@telit.com
TS-LATINAMERICA@telit.com
TS-APAC@telit.com

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For detailed information about where you can buy the Telit modules or for recommendations on accessories and components visit:
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Our aim is to make this guide as helpful as possible. Keep us informed of your comments and suggestions for improvements.
Telit appreciates feedback from the users of our information.

1.4. Document Organization

This document contains the following chapters:

Chapter 1: "Introduction" provides a scope for this document, target audience, contact and support information, and text conventions.

Chapter 2: "Overview" provides an overview of the document.

Chapter 3: "GL868 Mechanical Dimensions"

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Chapter 4: "GL868 Module Connections" deals with the pin out configuration and layout.

Chapter 5: "Hardware Commands" How to operate on the module via hardware.

Chapter 6: "Power supply" Power supply requirements and general design rules.

Chapter 7: "Antenna" The antenna connection and board layout design are the most important parts in the full product design.

Chapter 8: "Logic Level specifications" Specific values adopted in the implementation of logic levels for this module.

Chapter 9: "Serial ports" The serial port on the Telit GL868 is the core of the interface between the module and OEM hardware

Chapter 10: "Audio Section overview" Refers to the audio blocks of the Base Band Chip of the GL868 Telit Modules.

Chapter 11: "General Purpose I/O" How the general purpose I/O pads can be configured.

Chapter 12 "DAC and ADC Section" Deals with these two kind of converters.

Chapter 13: "Mounting the GL868 on the application board" Recommendations and specifics on how to mount the module on the user's board.

1.5. Text Conventions

Danger – This information MUST be followed or catastrophic equipment failure or bodily injury may occur.

Caution or Warning – Alerts the user to important points about integrating the module, if these points are not followed, the module and end user equipment may fail or malfunction.

Tip or Information – Provides advice and suggestions that may be useful when integrating the module.

All dates are in ISO 8601 format, i.e. YYYY-MM-DD.

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1.6. Related Documents

- Telit's GSM/GPRS Family Software User Guide, 1vv0300784
- Audio settings application note , 80000NT10007a
- Digital Voice Interface Application Note, 80000NT10004a
- GL868 Product description, 80370ST10082a
- SIM Holder Design Guides, 80000NT10001a
- AT Commands Reference Guide, 80000ST10025a
- Telit EVK2 User Guide, 1vv0300704

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2. Overview

The aim of this document is the description of some hardware solutions useful for developing a product with the Telit GL868 module.
In this document all the basic functions of a mobile phone will be taken into account; for each one of them a proper hardware solution will be suggested and eventually the wrong solutions and common errors to be avoided will be evidenced. Obviously this document cannot embrace the whole hardware solutions and products that may be designed. The wrong solutions to be avoided shall be considered as mandatory, while the suggested hardware configurations shall not be considered mandatory, instead the information given shall be used as a guide and a starting point for properly developing your product with the Telit GL868 module. For further hardware details that may not be explained in this document refer to the Telit GL868 Product Description document where all the hardware information is reported.

NOTICE:
The integration of the GSM/GPRS **GL868** cellular module within user application shall be done according to the design rules described in this manual.

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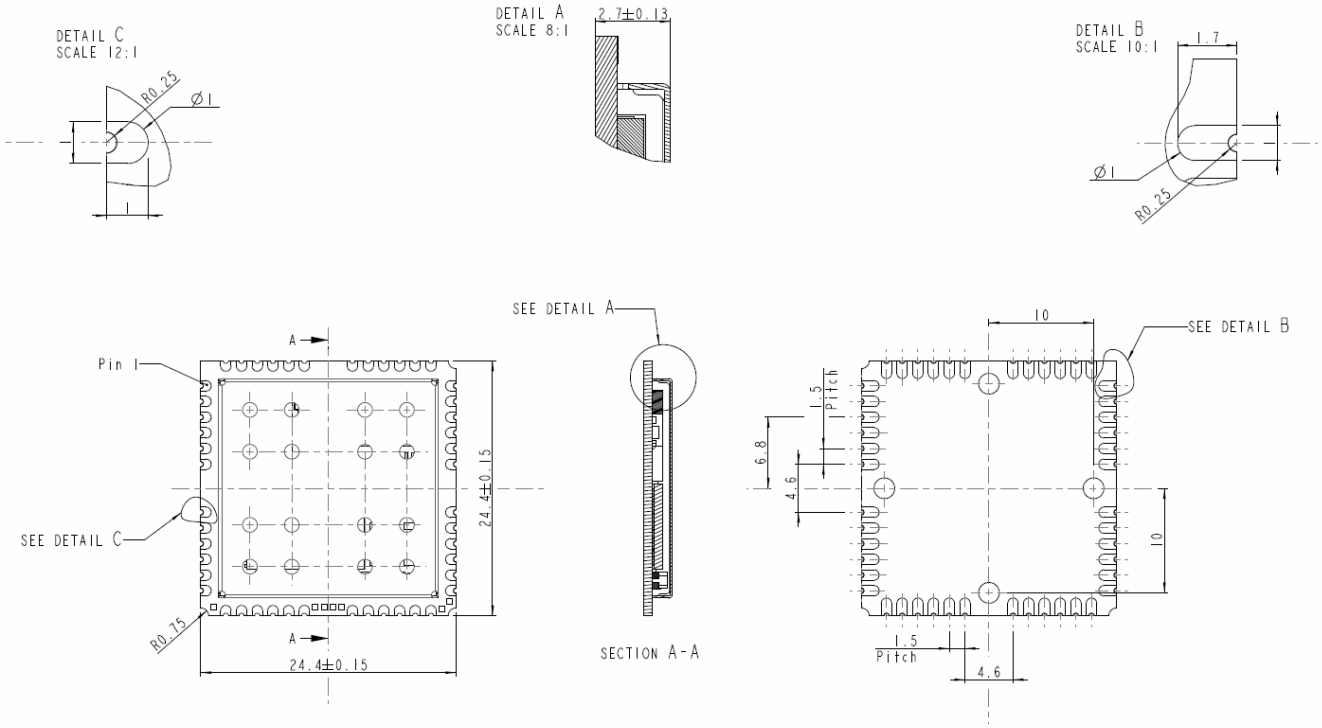
3. GL868 Mechanical Dimensions

The GL868 overall dimensions are:

- Length: 24.4 mm
- Width: 24.4 mm
- Thickness: 2.7 mm
- Weight 2.48 g



4. GL868 module connections

4.1. PIN-OUT

Pad	Signal	I/O	Function	Note	Type
Audio (not available on GL868-DUAL DATA ONLY version)					
20	EAR-	AO	Earphone signal output, phase -		Audio
21	EAR+	AO	Earphone signal output, phase +		Audio
22	MIC-	AI	Mic.signal input; phase-		Audio
24	MIC+	AI	Mic.signal input; phase+		Audio
23	AGND	-	Analog Ground		-
SIM card interface					
9	SIMVCC	-	External SIM signal – Power supply for the SIM		1,8 / 3V
10	SIMRST	O	External SIM signal – Reset		1,8 / 3V
11	SIMCLK	O	External SIM signal – Clock		1,8 / 3V
12	SIMIO	I/O	External SIM signal – Data I/O	4.7K Pull up	1,8 / 3V
X All GPI0 can be program med	SIMIN	I	Presence SIM input (See para 11.9)		CMOS 2.8V
Trace					
44	RX_AUX	I	Auxiliary UART (RX Data)		CMOS 2.8V
45	TX_AUX	O	Auxiliary UART (TX Data)		CMOS 2.8V
Prog. / Data + HW Flow Control					
1	C109/DCD/GPO	O	Output for Data carrier detect signal (DCD) to DTE / GP output		CMOS 2.8V
2	C125/RING/GPO	O	Output for Ring indicator signal (RI) to DTE / GP output		CMOS 2.8V
3	C107/DSR/GPO	O	Output for Data set ready signal (DSR) to DTE / GP output		CMOS 2.8V
4	C108/DTR/GPI	I	Input for Data terminal ready signal (DTR) from DTE / GP input		CMOS 2.8V
5	C105/RTS/GPI	I	Input for Request to send signal (RTS) from DTE / GP input		CMOS 2.8V
6	C106/CTS/GPO	O	Output for Clear to send signal (CTS) to DTE / GP output		CMOS 2.8V
7	C103/TXD	I	Serial data input (TXD) from DTE		CMOS 2.8V
8	C104/RXD	O	Serial data output to DTE		CMOS 2.8V
DAC and ADC					
13	ADC_IN1	AI	Analog/Digital converter input		A/D
14	ADC_IN2	AI	Analog/Digital converter input		A/D
15	DAC_OUT	AO	Digital/Analog converter output		D/A
Miscellaneous Functions					
30	VRTC	AO	VRTC Backup		Power
47	RESET*	I	Reset input		CMOS 1.8V
43	V_AUX / PWRMON	O	2.8V stabilized output Imax=100mA / Power ON monitor		Power Out 2.8V

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Pad	Signal	I/O	Function	Note	Type
34	Antenna	O	Antenna output – 50 Ω		RF
GPIO					
42	GPIO_01 / DVI_WA0	I/O	GPIO01 Configurable GPIO / Digital Audio Interface (WA0)		CMOS 2.8V
41	GPIO_02 / JDR / DVI_RX	I/O	GPIO02 Configurable GPIO / Jammer Detect Report / Digital Audio Interface (RX)		CMOS 2.8V
40	GPIO_03 / DVI_TX	I/O	GPIO03 Configurable GPIO / Digital Audio Interface (TX)		CMOS 2.8V
39	GPIO_04 / TX Disable / DVI_CLK	I/O	GPIO04 Configurable GPIO / TX Disable input / Digital Audio Interface (CLK)		CMOS 2.8V
29	GPIO_05 / RFTXMON	I/O	GPIO05 Configurable GPIO / Transmitter ON monitor		CMOS 2.8V
28	GPIO_06 / ALARM	I/O	GPIO06 Configurable GPIO / ALARM		CMOS 2.8V
27	GPIO_07 / BUZZER	I/O	GPIO07 Configurable GPIO / Buzzer		CMOS 2.8V
26	GPIO_08 / STAT_LED	I/O	GPIO08 Configurable GPIO / STAT LED		CMOS 2.8V
Power Supply					
38	VBATT	-	Main power supply (Baseband)		Power
37	VBATT_PA	-	Main power supply (Radio PA)		Power
23	AGND	-	AF Signal Ground (see audio section)		AF Signal
32	GND	-	Ground		Power
33	GND	-	Ground		Power
35	GND	-	Ground		Power
36	GND	-	Ground		Power
46	GND	-	Ground		Power
RESERVED					
48		-			
16		-			
17		-			
18		-			
19		-			
25		-			
31		-			

WARNING:

Reserved pins must not be connected.

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NOTE:

If not used, almost all pins should be left disconnected. The only exceptions are the following pins:

pin	signal
38, 37	VBATT & VBATT_PA
32, 33, 35, 36, 46	GND
23	AGND
7	TXD
8	RXD
5	RTS
43	V_AUX / PWRMON
47	RESET*
45	TX_AUX
44	RX_AUX

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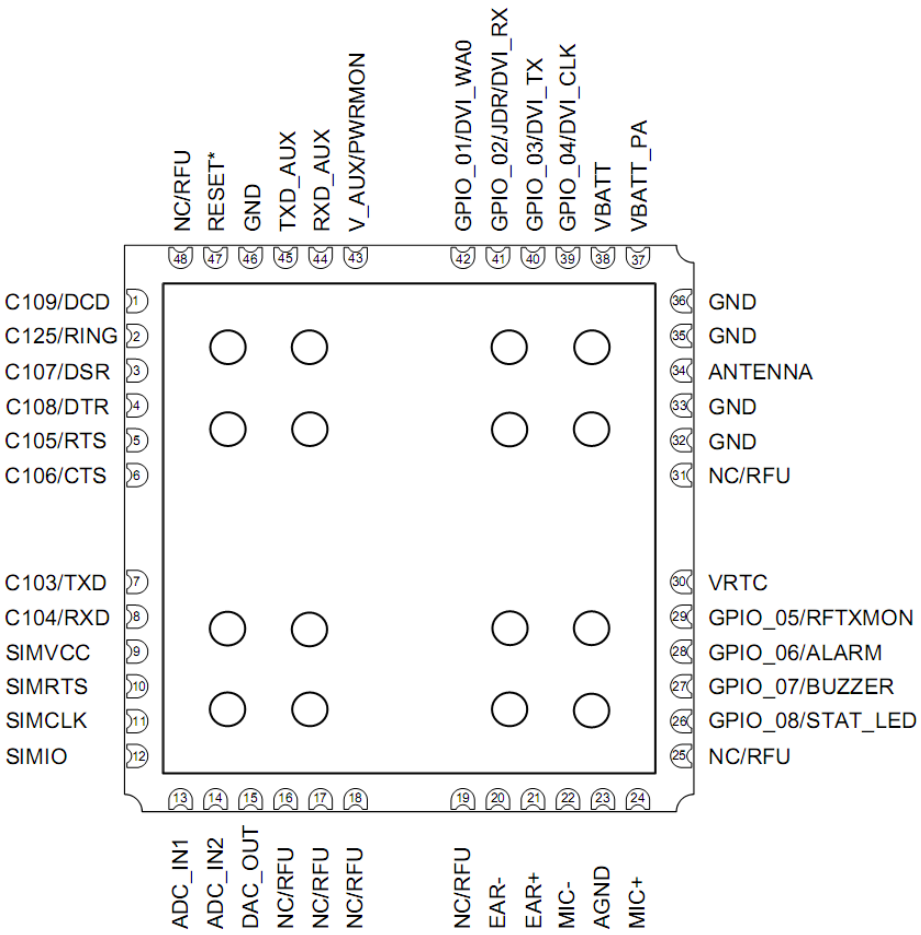
4.2. Pin Layout

TOP VIEW



NOTE:

The pin defined as NC/RFU has to be considered RESERVED and don't connect on any pin in the application.

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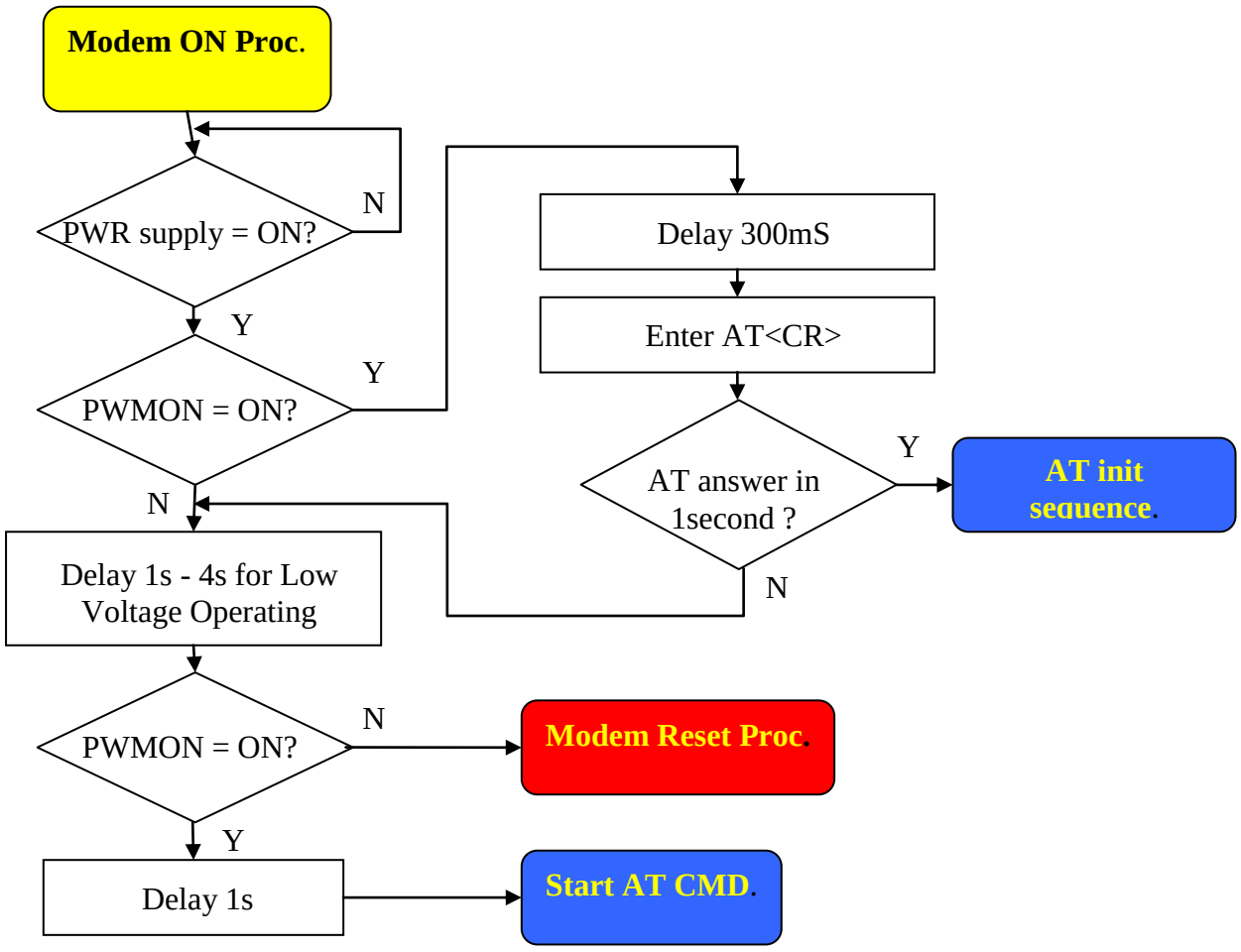
5. Hardware Commands

5.1. Auto-Turning ON the GL868

To Auto-turn on the GL868, the power supply must be applied on the power pins VBATT and VBATT_PA, after 1000 m-seconds, the V_AUX / PWRMON pin will be at the high logic level and the module can be consider fully operating.

When the power supply voltage is lower than 3.4V, after 4000 m-seconds, the V_AUX / PWRMON pin will be at the high logic level and the module can be consider fully operating.

The following flow chart shows the proper turn on procedure:



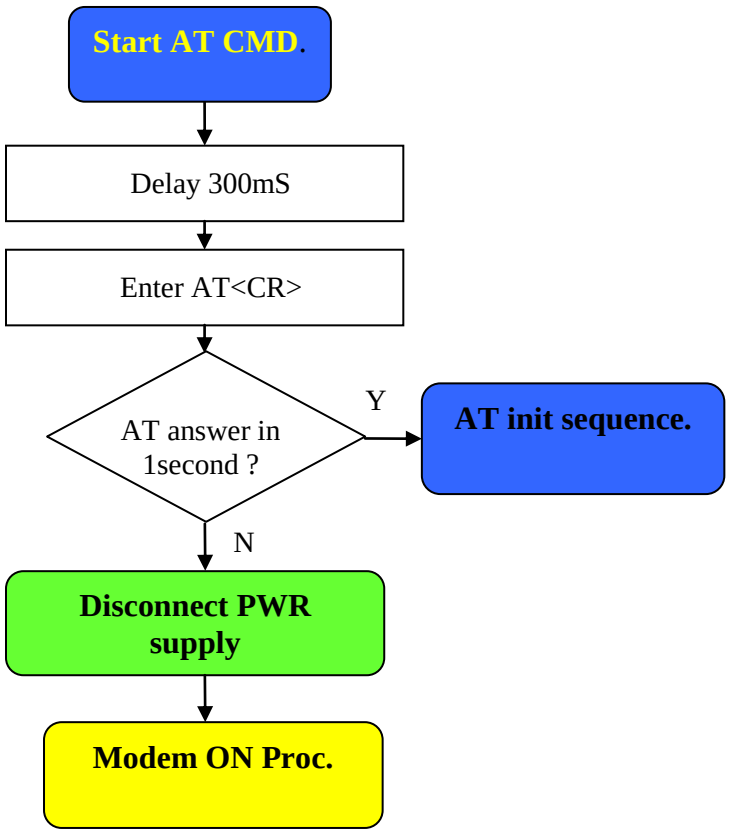
NOTE:

The power supply on the pins VBATT and VBATT_PA must be applied at the same time or for the special application in the first apply the VBATT_PA and in second time apply VBATT, never vice versa in this case can be damage the unit.

NOTE:

In order to avoid a back powering effect it is recommended to avoid having any HIGH logic level signal applied to the digital pins of the GL868 when the module is powered OFF or during an ON/OFF transition.

A flow chart showing the AT command managing procedure is displayed below:



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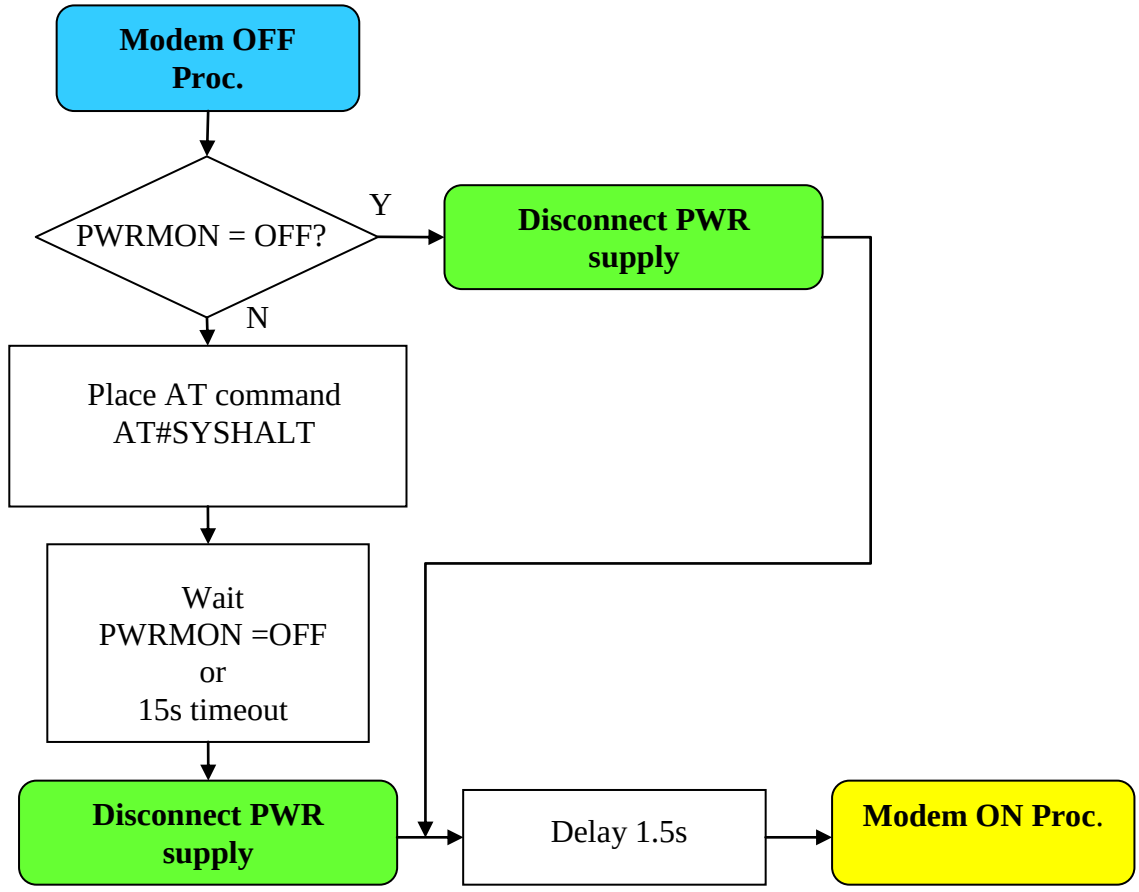
5.2. Turning OFF the GL868

Turning off of the device can be done in two ways:

- General turn OFF
- Processor turn OFF

General turn OFF – disconnect the power supply from the both power pins VBATT and VBATT_PA at the same time. In this case all parts of the module are in OFF condition, any power consumption is present.
Processor turn OFF – disconnect the power supply only from the power pin VBATT, the power pin VBATT_PA can be connected to power supply, in this case a low, typical 2uA max 20uA, power consumption is present.
Before any of both OFF procedure will be applied, the AT#SYSHALT AT command must be send (see AT Commands Reference Guide, 80000ST10025a), after the OK response message, check the V_AUX / PWRMON pin, when the logic level is low the module can be consider fully not operating and at this moment is possible disconnect the Power Supply.
The following flow chart shows the proper turnoff procedure:



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TIP:
To check if the device has been powered off, the hardware line PWRMON must be monitored. The device is powered off when PWRMON goes low.

NOTE:
In order to avoid a back powering effect it is recommended to avoid having any HIGH logic level signal applied to the digital pins of the GL868 when the module is powered OFF or during an ON/OFF transition.

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5.3. Resetting the GL868

5.3.1. Hardware Unconditional restart

WARNING:

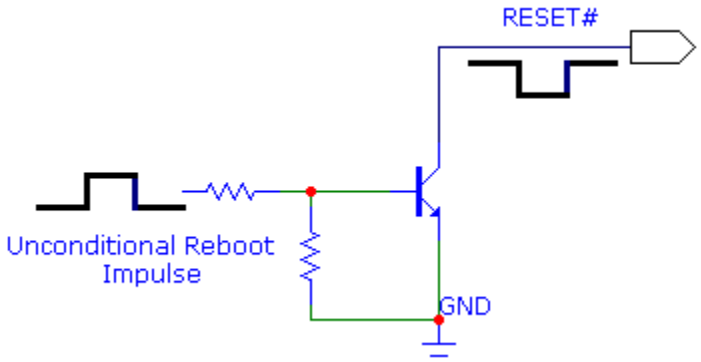
The hardware unconditional Restart must not be used during normal operation of the device since it does not detach the device from the network. It shall be kept as an emergency exit procedure to be done in the rare case that the device gets stacked waiting for some network or SIM responses.

To unconditionally reboot the GL868, the pad RESET* must be tied low for at least 200 milliseconds and then released.

NOTE:
Do not use any pull up resistor on the RESET* line nor any totem pole digital output. Using pull up resistor may bring to latch up problems on the GL868 power regulator and improper functioning of the module. The line RESET* must be connected only in open collector configuration; the transistor must be connected as close as possible to the RESET* pin.

TIP:
The unconditional hardware restart must always be implemented on the boards and the software must use it as an emergency exit procedure.

A simple circuit to do it is:



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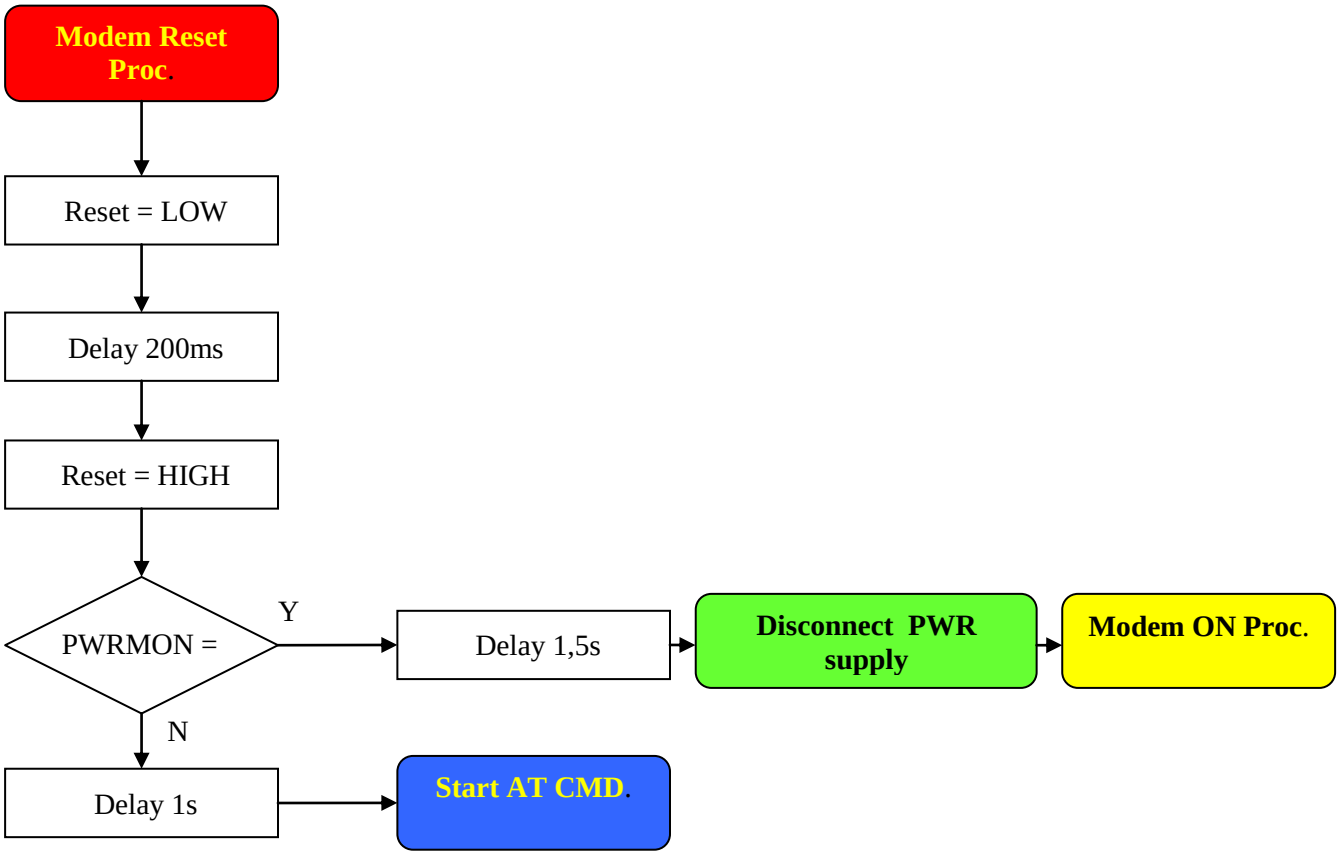
In the following flow chart is detailed the proper restart procedure:



NOTE:

In order to avoid a back powering effect it is recommended to avoid having any HIGH logic level signal applied to the digital pins of the GL868 when the module is powered OFF or during an ON/OFF transition.

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6. Power Supply

The power supply circuitry and board layout are a very important part in the full product design and they strongly reflect on the product overall performances, hence read carefully the requirements and the guidelines that will follow for a proper design.

6.1. Power Supply Requirements

The external power supply must be connected to VBATT & VBATT_PA signals and must fulfill the following requirements:

POWER SUPPLY	
Nominal Supply Voltage	3.8 V
Normal Operating Voltage Range	3.4 V÷ 4.20 V
Extended Operating Voltage Range	3.22 V÷ 4.50 V

NOTE:

The Operating Voltage Range MUST never be exceeded; care must be taken in order to fulfil min/max voltage requirement.

NOTE:

Overshoot voltage (regarding MAX Extended Operating Voltage) and drop in voltage (regarding MIN Extended Operating Voltage) MUST never be exceeded;

The “Extended Operating Voltage Range” can be used only with completely assumption and application of the HW User guide suggestions.

NOTE:

When the power supply voltage is lower than 3.4V, after 4000 m-seconds, the V_AUX / PWRMON pin will be at the high logic level and the module can be consider fully operating. See para 5.1.

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6.2. Power Consumption

The GL868 power consumptions are:

Mode	Average (mA)	Mode description
SWITCHED OFF		Module power supplied only on VBATT_PA pin, the VBATT pin is not power supplied.
Switched Off	Typical 2uA max 20uA	
Switched Off with AT#SYSHALT	<650uA	Module power supplied on VBATT_PA pin and VBATT pin, the at command AT#SYSHALT is applied.
IDLE mode		
AT+CFUN=1	21,0	Normal mode: full functionality of the module
AT+CFUN=4	18,0	Disabled TX and RX; module is not registered on the network
AT+CFUN=0 or =5	3,9	Paging Multiframe 2
	2,5	Paging Multiframe 3
	2,4	Paging Multiframe 4
	1,5	Paging Multiframe 9
CSD TX and RX mode		GSM VOICE CALL
GSM900 CSD PL5	230	
DCS1800 CSD PL0	180	
GPRS (class 8) 1TX		GPRS Sending data mode
GSM900 PL5	225	
DCS1800 PL0	175	
GPRS (class 10) 2TX		GPRS Sending data mode
GSM900 PL5	360	
DCS1800 PL0	300	

The GSM system is made in a way that the RF transmission is not continuous, else it is packed into bursts at a base frequency of about 216 Hz, and the relative current peaks can be as high as about 2A. Therefore the power supply has to be designed in order to withstand with these current peaks without big voltage drops; this means that both the electrical design and the board layout must be designed for this current flow.
If the layout of the PCB is not well designed a strong noise floor is generated on the ground and the supply; this will reflect on all the audio paths producing an audible annoying noise at 216 Hz; if the voltage drop during the peak current absorption is too much, then the device may even shutdown as a consequence of the supply voltage drop.

NOTE:

The electrical design for the Power supply should be made ensuring it will be capable of a peak current output of at least 2 A.

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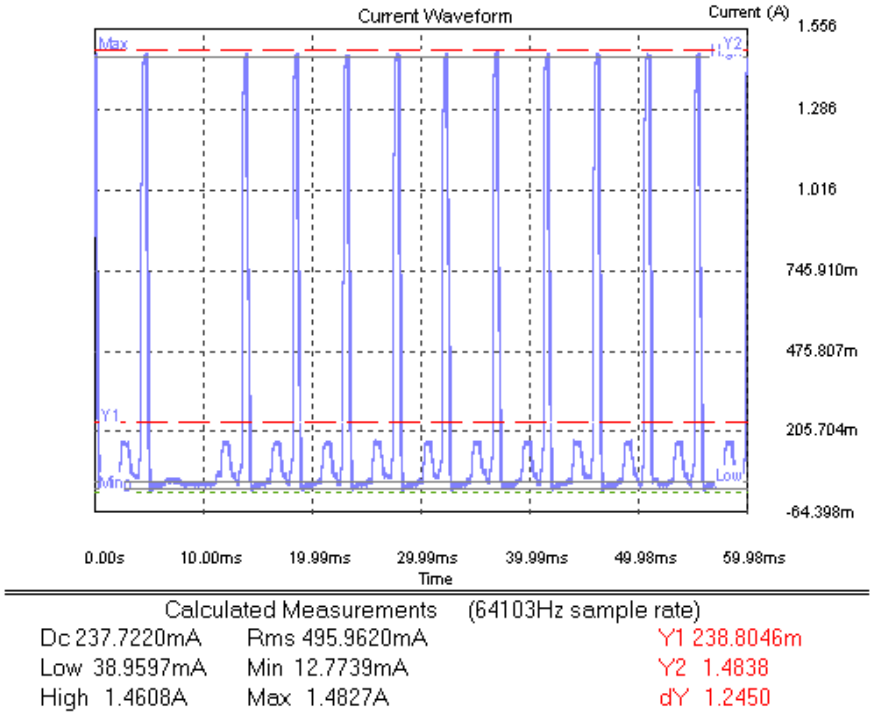
6.2.1. Power consumption Plots

This document section is showing the typical Current consumption plots (using Agilent 66319D) in the normal working conditions of the module.

GSM900 – Voice Call – Power level 5



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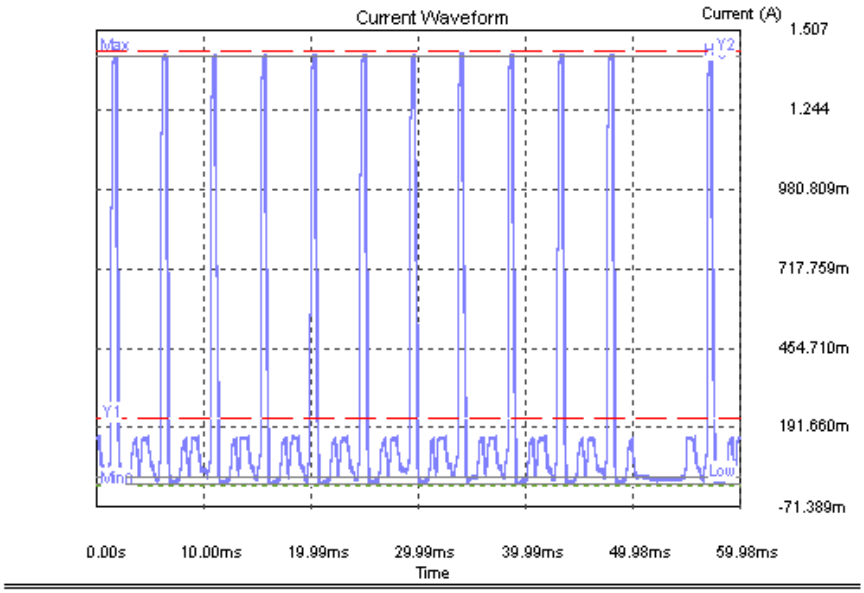
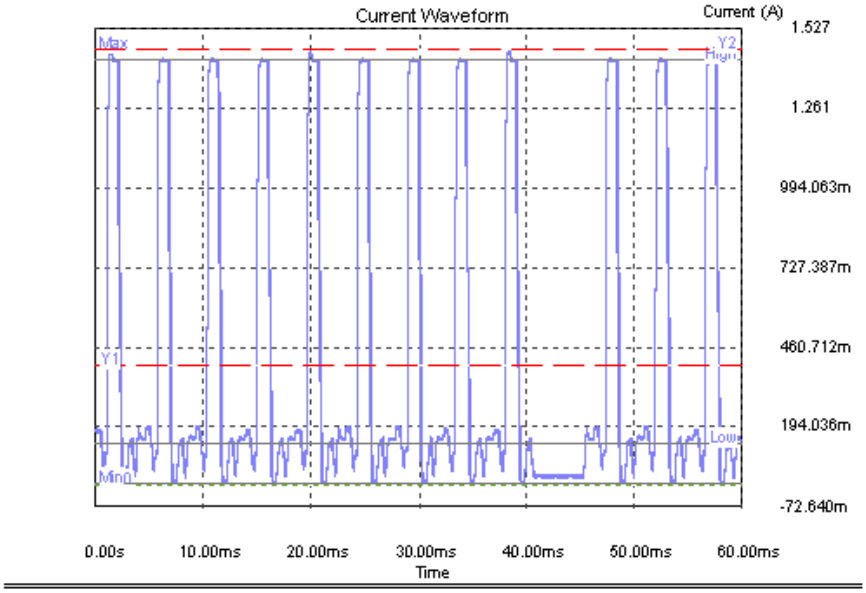
GSM900 – GPRS Call – Power level 5 - 1 Slot TX



Calculated Measurements (64103Hz sample rate)

Dc 223.0320mA	Rms 465.6530mA	Y1 223.2308m
Low 28.3425mA	Min 3.7677mA	Y2 1.4360
High 1.4184A	Max 1.4353A	dY 1.2128

GSM900 – GPRS Call – Power level 5 - 2 Slot TX, 3 Slot RX



Calculated Measurements (64103Hz sample rate)

Dc 402.5160mA	Rms 674.0740mA	Y1 402.2942m
Low 137.8680mA	Min 3.5532mA	Y2 1.4556
High 1.4208A	Max 1.4549A	dY 1.0533

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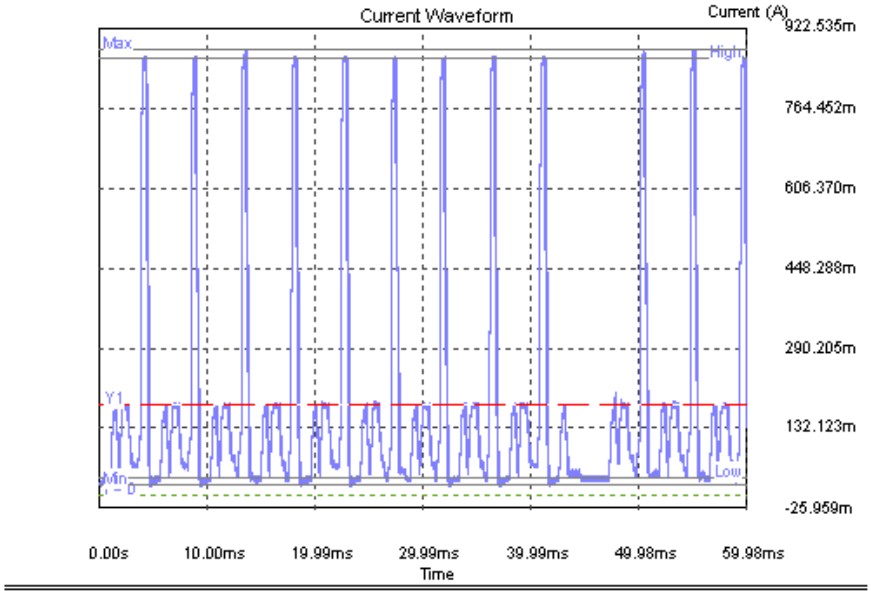
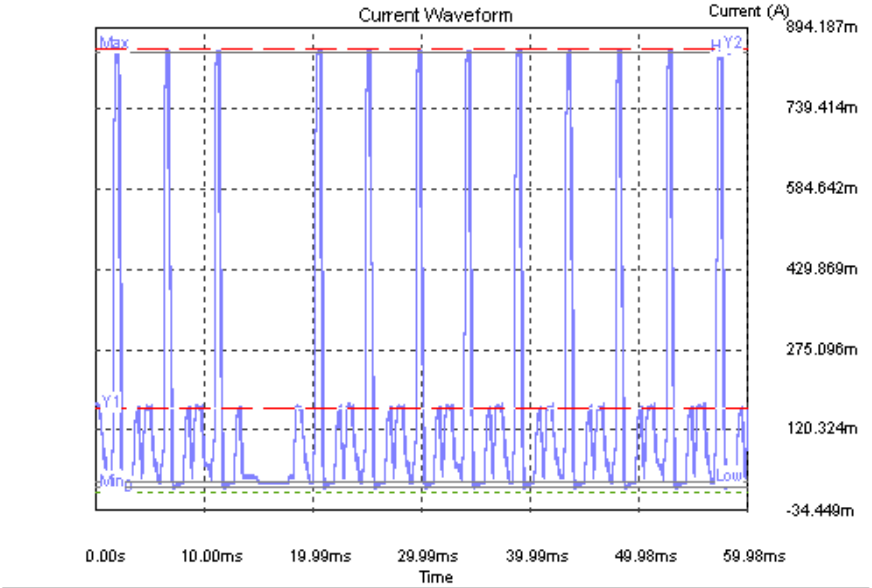
DCS1800 – Voice Call – Power level 0



Calculated Measurements (64103Hz sample rate)

Dc 177.1700mA	Rms 299.8590mA	Y1 177.6604m
Low 34.7802mA	Min 19.2070mA	Y2 1.4838
High 861.7810mA	Max 879.5190mA	dY 1.3061

DCS1800 – GPRS Call – Power level 0 – 1 Slot TX



Calculated Measurements (64103Hz sample rate)

Dc 160.0650mA	Rms 287.8460mA	Y1 160.0650m
Low 22.0351mA	Min 9.7719mA	Y2 852.4848m
High 846.7840mA	Max 852.0720mA	dY 692.4199m

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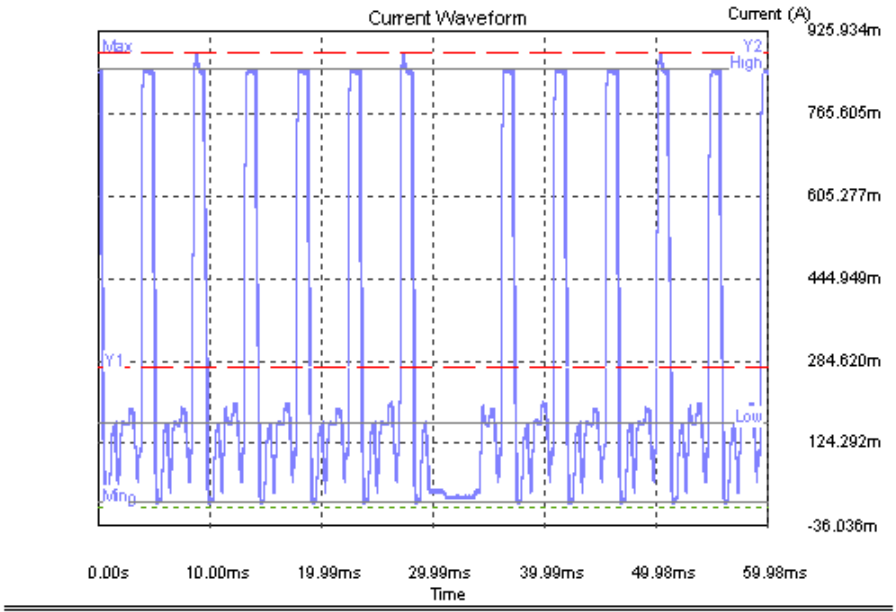
PCS1900 – GPRS Call – Power level 0 - 2 Slot TX, 3 Slot RX



Calculated Measurements (64103Hz sample rate)

Dc 274.4900mA	Rms 412.9800mA	Y1 274.5464m
Low 163.0430mA	Min 9.7719mA	Y2 882.7347m
High 850.5330mA	Max 882.3070mA	dY 608.1882m

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6.3. General Design Rules

The principal guidelines for the Power Supply Design embrace three different design steps:
the electrical design
the thermal design
the PCB layout.

6.3.1. Electrical Design Guidelines

The electrical design of the power supply depends strongly from the power source where this power is drained. We will distinguish them into three categories:
+5V input (typically PC internal regulator output)
+12V input (typically automotive)
Battery

6.3.1.1. + 5V input Source Power Supply Design Guidelines

The desired output for the power supply is 3.8V, hence there's not a big difference between the input source and the desired output and a linear regulator can be used. A switching power supply will not be suited because of the low drop out requirements.
When using a linear regulator, a proper heat sink shall be provided in order to dissipate the power generated.
A Bypass low ESR capacitor of adequate capacity must be provided in order to cut the current absorption peaks close to the GL868, a 100µF tantalum capacitor is usually suited.
Make sure the low ESR capacitor on the power supply output (usually a tantalum one) is rated at least 10V.
A protection diode should be inserted close to the power input, in order to save the GL868 from power polarity inversion.

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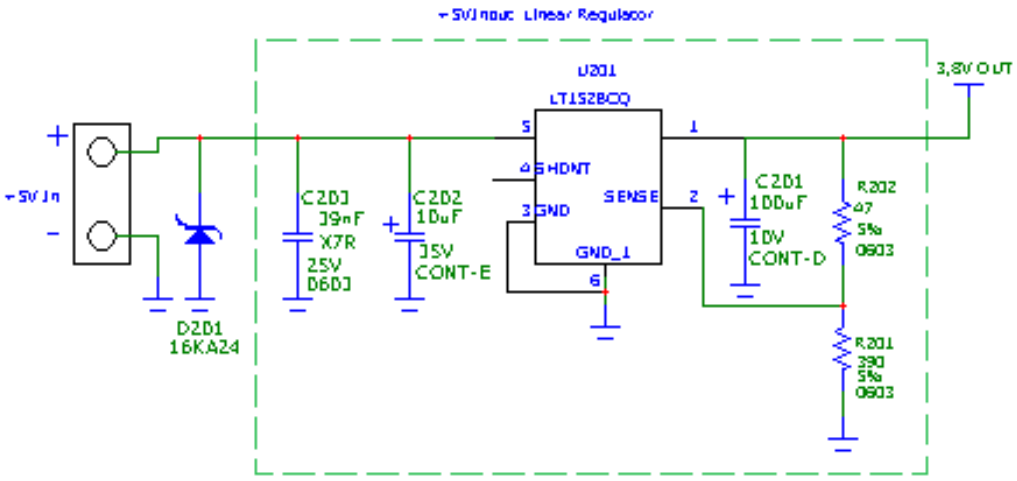
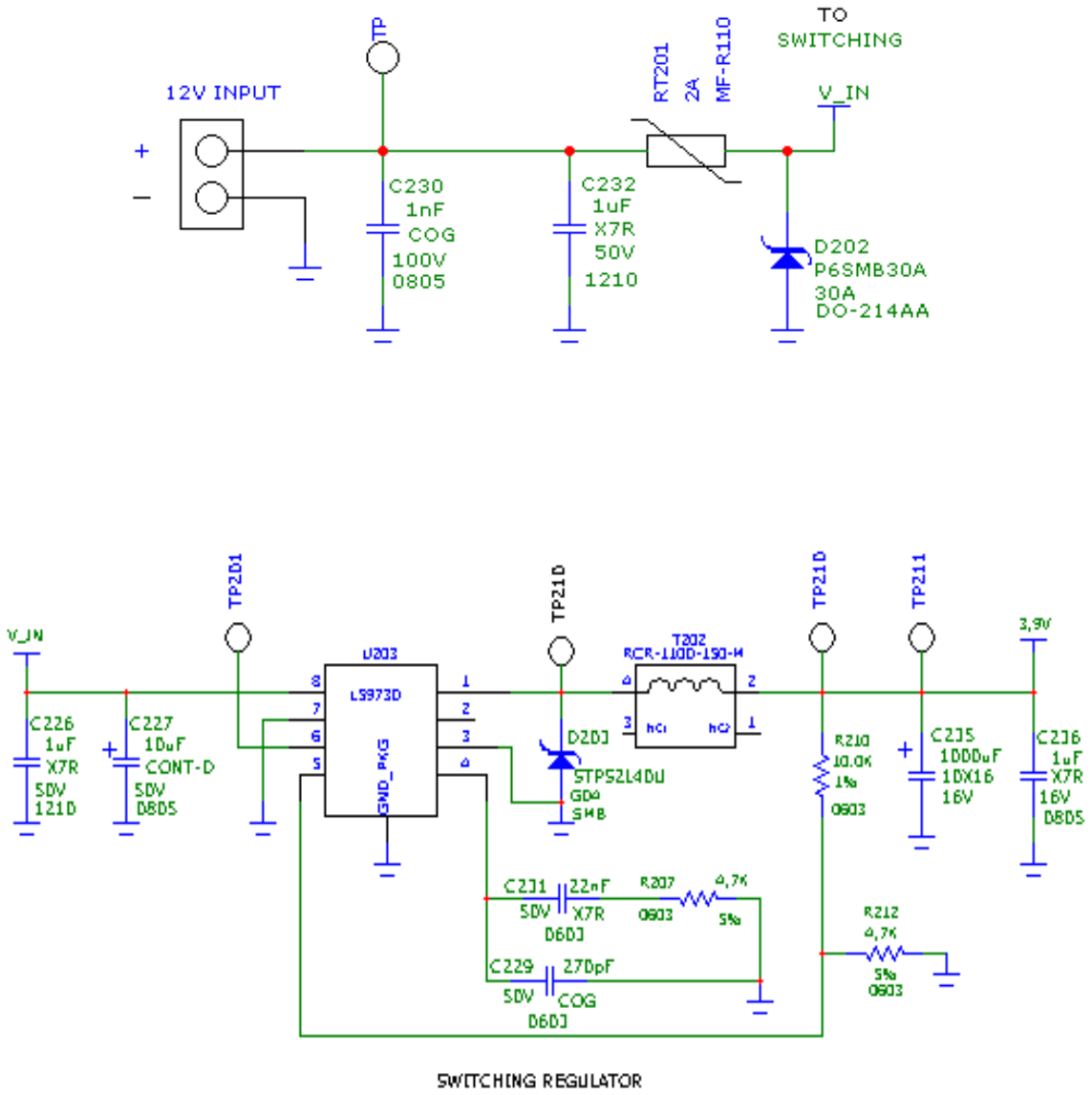
An example of linear regulator with 5V input is:



6.3.1.2. + 12V input Source Power Supply Design Guidelines

The desired output for the power supply is 3.8V, hence due to the big difference between the input source and the desired output, a linear regulator is not suited and shall not be used. A switching power supply will be preferable because of its better efficiency especially with the 2A peak current load represented by the GL868.
When using a switching regulator, a 500kHz or more switching frequency regulator is preferable because of its smaller inductor size and its faster transient response. This allows the regulator to respond quickly to the current peaks absorption.
In any case the frequency and Switching design selection is related to the application to be developed due to the fact the switching frequency could also generate EMC interferences.
For car PB battery the input voltage can rise up to 15,8V and this should be kept in mind when choosing components: all components in the power supply must withstand this voltage.
A Bypass low ESR capacitor of adequate capacity must be provided in order to cut the current absorption peaks, a 100µF tantalum capacitor is usually suited.
Make sure the low ESR capacitor on the power supply output (usually a tantalum one) is rated at least 10V.
For Car applications a spike protection diode should be inserted close to the power input, in order to clean the supply from spikes.
A protection diode should be inserted close to the power input, in order to save the GL868 from power polarity inversion. This can be the same diode as for spike protection.

An example of switching regulator with 12V input is in the below schematic (split in 2 parts):



6.3.1.3. Battery Source Power Supply Design Guidelines

The desired nominal output for the power supply is 3.8V and the maximum voltage allowed is 4.2V, hence a single 3.7V Li-Ion cell battery type is suited for supplying the power to the Telit GL868 module.

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WARNING:

The three cells Ni/Cd or Ni/MH 3,6 V Nom. battery types or 4V PB types ***MUST NOT BE USED DIRECTLY*** since their maximum voltage can rise over the absolute maximum voltage for the GL868 and damage it.

NOTE:

DON'T USE any Ni-Cd, Ni-MH, and Pb battery types directly connected with GL868. Their use can lead to overvoltage on the GL868 and damage it. USE ONLY Li-Ion battery types.

A Bypass low ESR capacitor of adequate capacity must be provided in order to cut the current absorption peaks, a 100µF tantalum capacitor is usually suited.
Make sure the low ESR capacitor (usually a tantalum one) is rated at least 10V.
A protection diode should be inserted close to the power input, in order to save the GL868 from power polarity inversion. Otherwise the battery connector should be done in a way to avoid polarity inversions when connecting the battery.
The battery capacity must be at least 500mAh in order to withstand the current peaks of 2A; the suggested capacity is from 500mAh to 1000mAh.

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6.3.2. Thermal Design Guidelines

The thermal design for the power supply heat sink should be done with the following specifications:
See para 7.2 Power Consumption

NOTE:

The average consumption during transmissions depends on the power level at which the device is requested to transmit by the network. The average current consumption hence varies significantly.

Considering the very low current during idle, especially if Power Saving function is enabled, it is possible to consider from the thermal point of view that the device absorbs current significantly only during calls.
For the heat generated by the GL868, you can consider it to be during transmission 1W max during CSD/VOICE calls and 2W max during class10 GPRS upload.
This generated heat will be mostly conducted to the ground plane under the GL868; you must ensure that your application can dissipate it.

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6.3.3. Power Supply PCB layout Guidelines

As seen on the electrical design guidelines the power supply shall have a low ESR capacitor on the output to cut the current peaks and a protection diode on the input to protect the supply from spikes and polarity inversion. The placement of these components is crucial for the correct working of the circuitry. A misplaced component can be useless or can even decrease the power supply performances.

The Bypass low ESR capacitor must be placed close to the Telit GL868 power input pads or in the case the power supply is a switching type it can be placed close to the inductor to cut the ripple provided the PCB trace from the capacitor to the GL868 is wide enough to ensure a dropless connection even during the 2A current peaks.
The protection diode must be placed close to the input connector where the power source is drained.
The PCB traces from the input connector to the power regulator IC must be wide enough to ensure no voltage drops occur when the 2A current peaks are absorbed. Note that this is not made in order to save power loss but especially to avoid the voltage drops on the power line at the current peaks frequency of 216 Hz that will reflect on all the components connected to that supply, introducing the noise floor at the burst base frequency. For this reason while a voltage drop of 300-400 mV may be acceptable from the power loss point of view, the same voltage drop may not be acceptable from the noise point of view. If your application doesn't have audio interface but only uses the data feature of the Telit GL868, then this noise is not so disturbing and power supply layout design can be more forgiving.
The PCB traces to the GL868 and the Bypass capacitor must be wide enough to ensure no significant voltage drops occur when the 2A current peaks are absorbed. This is for the same reason as previous point. Try to keep this trace as short as possible.
The PCB traces connecting the Switching output to the inductor and the switching diode must be kept as short as possible by placing the inductor and the diode very close to the power switching IC (only for switching power supply). This is done in order to reduce the radiated field (noise) at the switching frequency (100-500 kHz usually).
The use of a good common ground plane is suggested.
The placement of the power supply on the board should be done in such a way to guarantee that the high current return paths in the ground plane are not overlapped to any noise sensitive circuitry as the microphone amplifier/buffer or earphone amplifier.
The power supply input cables should be kept separate from noise sensitive lines such as microphone/earphone cables.

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7. Antenna

The antenna connection and board layout design are the most important aspect in the full product design as they strongly affect the product overall performances, hence read carefully and follow the requirements and the guidelines for a proper design.

7.1. GSM Antenna Requirements

As suggested on the Product Description the antenna and antenna transmission line on PCB for a Telit GL868 device shall fulfil the following requirements:

ANTENNA REQUIREMENTS	
Frequency range	880-960 MHz and 1710-1885MHz with SWR <2:1 (or equivalently 10dB return loss)
Gain	1.4dBi @900 and 3dBi @1800
Impedance	50 Ohm
Input power	> 2 W
VSWR absolute max	≤ 10:1 (limit to avoid permanent damage)
VSWR recommended	≤ 2:1 (limit to fulfil all regulatory requirements)

When using the GL868, since there's no antenna connector on the module, the antenna must be connected to the GL868 antenna pad (**pin 34**) by means of a transmission line implemented on the PCB.

In the case the antenna is not directly connected at the antenna pad of the GL868, then a PCB line is needed in order to connect with it or with its connector.

This line of transmission shall fulfill the following requirements:

ANTENNA LINE ON PCB REQUIREMENTS	
Characteristic Impedance	50 Ohm
Max Attenuation	0,3 dB
Coupling with other signals shall be avoided	
Cold End (Ground Plane) of antenna shall be equipotential to the GL868 ground pins	

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7.2. GSM Antenna – PCB line Guidelines

Make sure that the transmission line's characteristic impedance is 50Ω ;
Keep the length of line on the PCB as short as possible, since the antenna line loss shall be less than about 0,3 dB;
Line geometry should have uniform characteristics, constant cross section, avoid meanders and abrupt curves;
Any kind of suitable geometry / structure (Microstrip, Stripline, Coplanar, Grounded Coplanar Waveguide...) can be used for implementing the printed transmission line afferent the antenna;
If a Ground plane is required in line geometry, that plane has to be continuous and sufficiently extended, so the geometry can be as similar as possible to the related canonical model;
Keep, if possible, at least one layer of the PCB used only for the Ground plane. If possible, use this layer as reference Ground plane for the transmission line;
It is wise to surround (on both sides) the PCB transmission line with Ground, avoid having other signal tracks facing directly the antenna line track.
Avoid crossing any un-shielded transmission line footprint with other signal tracks on different layers;
The ground surrounding the antenna line on PCB has to be strictly connected to the main Ground Plane by means of via holes (once per 2mm at least), placed close to the ground edges facing line track;
Place EM noisy devices as far as possible from GL868 antenna line;
Keep the antenna line far away from the GL868 power supply lines;
If EM noisy devices are present on the PCB hosting the GL868, such as fast switching ICs, take care of the shielding of the antenna line by burying it inside the layers of PCB and surround it with Ground planes, or shield it with a metal frame cover.
If EM noisy devices are not present around the line, the use of geometries like Microstrip or Grounded Coplanar Waveguide has to be preferred, since they typically ensure less attenuation if compared to a Stripline having same length;

7.3. GSM Antenna – Installation Guidelines

Install the antenna in a place covered by the GSM signal.
Antenna shall not be installed inside metal cases
Antenna shall be installed also according Antenna manufacturer instructions.

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8. Logic level specifications

Where not specifically stated, all the interface circuits work at 2.8V CMOS logic levels. The following table shows the logic level specifications used in the GL868 interface circuits:

Absolute Maximum Ratings -Not Functional

Parameter	Min	Max
Input level on any digital pin (CMOS 2.8) when on	-0.3V	+3.1V
Input level on any digital pin (CMOS 1.8) when on	-0.3V	+2.1V
Input voltage on analog pins when on	-0.3V	+3.0 V

Operating Range - Interface levels (2.8V CMOS)

Level	Min	Max
Input high level	2.1V	3.1V
Input low level	0V	0.5V
Output high level	2.2V	3.1V
Output low level	0V	0.35V

For 1.8V signals:

Operating Range - Interface levels (1.8V CMOS)

Level	Min	Max
Input high level	1.6V	2.0V
Input low level	0V	0.4V
Output high level	1,65V	2.0V
Output low level	0V	0.35V

Current characteristics

Level	Typical
Output Current	1mA
Input Current	1uA

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8.1. Reset signal

Signal	Function	I/O	pin
RESET*	Phone reset	I	47

RESET* is used to reset the GL868. Whenever this signal is pulled low, the GL868 is reset. When the device is reset it stops any operation. After the release of the reset GL868 is unconditionally shut down, without doing any detach operation from the network where it is registered. This behaviour is not a proper shut down because any GSM device is requested to issue a detach request on turn off. For this reason the Reset signal must not be used to normally shutting down the device, but only as an emergency exit in the rare case the device remains stuck waiting for some network response.

The RESET* is internally controlled on start-up to achieve always a proper power-on reset sequence, so there's no need to control this pin on start-up. It may only be used to reset a device already on that is not responding to any command.

NOTE:

Do not use this signal to power OFF the GL868. Use the ON/OFF procedure to perform this function.

Reset Signal Operating levels:

Signal	Min	Max
RESET* Input high	1.8V[1]	2.1V
RESET* Input low	0V	0.2V

If unused, this signal may be left unconnected. If used, then it must always be connected with an open collector transistor, to permit to the internal circuitry the power on reset and under voltage lockout functions.

[1] this signal is internally pulled up so the pin can be left floating if not used

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9. Serial Ports

The serial port on the GL868 is the core of the interface between the module and OEM hardware.
2 serial ports are available on the module:
MODEM SERIAL PORT 1 (MAIN) → for AT commands and Data
MODEM SERIAL PORT 2 (AUX) → for AT commands or Debug

9.1. MODEM SERIAL PORT

Several configurations can be designed for the serial port on the OEM hardware, but the most common are:
RS232 PC com port
microcontroller UART @ 2.8V - 3V (Universal Asynchronous Receive Transmit)
microcontroller UART @ 5V or other voltages different from 2.8V

Depending from the type of serial port on the OEM hardware a level translator circuit may be needed to make the system work. The only configuration that doesn't need a level translation is the 2.8V UART.
The serial port on the GL868 is a +2.8V UART with all the 7 RS232 signals. It differs from the PC-RS232 in the signal polarity (RS232 is reversed) and levels. The levels for the GL868 UART are the CMOS levels:

Absolute Maximum Ratings -Not Functional

Parameter	Min	Max
Input level on any digital pad when on	-0.3V	+3.1V
Input voltage on analog pads when on	-0.3V	+3.1V

Operating Range - Interface levels (2.8V CMOS)

Level		Min	Max
Input high level	VIH	2.1V	3.1 V
Input low level	VIL	0V	0.5V
Output high level	VOH	2.2V	3.1V
Output low level	VOL	0V	0.35V

The signals of the GL868 serial port are:

RS232 Pin Number	Signal	GL868 Pad Number	Name	Usage
1	DCD - dcd_uart	1	Data Carrier Detect	Output from the GL868 that indicates the carrier presence

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2	RXD - tx_uart	8	Transmit line *see Note	Output transmit line of GL868 UART
3	TXD - rx_uart	7	Receive line *see Note	Input receive of the GL868 UART
4	DTR - dtr_uart	4	Data Terminal Ready	Input to the GL868 that controls the DTE READY condition
5	GND	32, 33, 35, 36, 46	Ground	ground
6	DSR - dsr_uart	3	Data Set Ready	Output from the GL868 that indicates the module is ready
7	RTS -rts_uart	5	Request to Send	Input to the GL868 that controls the Hardware flow control
8	CTS - cts_uart	6	Clear to Send	Output from the GL868 that controls the Hardware flow control
9	RI - ri_uart	2	Ring Indicator	Output from the GL868 that indicates the incoming call condition

NOTE:

According to V.24, RX/TX signal names are referred to the application side, therefore on the GL868 side these signal are on the opposite direction: TXD on the application side will be connected to the receive line (here named TXD/ rx_uart) of the GL868 serial port and viceversa for RX.

NOTE:

For a minimum implementation, only the TXD and RXD lines can be connected, the other lines can be left open provided a software flow control is implemented.

NOTE:

In order to avoid a back powering effect it is recommended to avoid having any HIGH logic level signal applied to the digital pins of the GE868 when the module is powered off or during an ON/OFF transition.

9.2. RS232 level translation

In order to interface the GL868 with a PC com port or a RS232 (EIA/TIA-232) application a level translator is required. This level translator must:

- invert the electrical signal in both directions;
- change the level from 0/2.8V to +15/-15V .

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Actually, the RS232 UART 16450, 16550, 16650 & 16750 chipsets accept signals with lower levels on the RS232 side (EIA/TIA-562), allowing a lower voltage-multiplying ratio on the level translator. Note that the negative signal voltage must be less than 0V and hence some sort of level translation is always required.
The simplest way to translate the levels and invert the signal is by using a single chip level translator. There are a multitude of them, differing in the number of drivers and receivers and in the levels (be sure to get a true RS232 level translator not a RS485 or other standards).
By convention the driver is the level translator from the 0-2.8V UART to the RS232 level. The receiver is the translator from the RS232 level to 0-2.8V UART.
In order to translate the whole set of control lines of the UART you will need:

- 5 drivers
- 3 receivers

NOTE:

The digital input lines working at 2.8V CMOS have an absolute maximum input voltage of 3.0V; therefore the level translator IC shall not be powered by the +3.8V supply of the module. Instead, it must be powered from a +2.7V / +2.9V (dedicated) power supply.

This is because in this way the level translator IC outputs on the module side (i.e. GL868 inputs) will work at +3.8V interface levels, damaging the module inputs.

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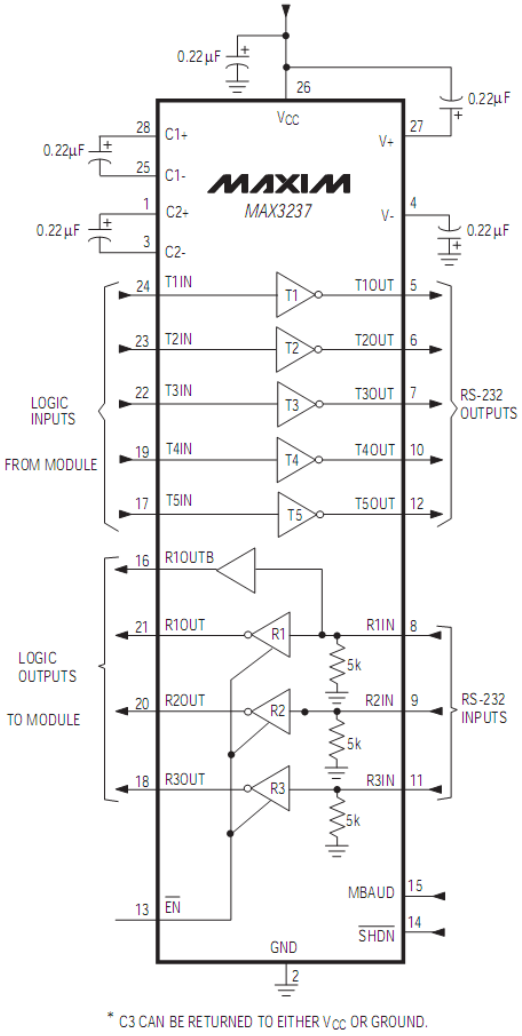
An example of level translation circuitry of this kind is:



The example is done with a MAXIM MAX3237 Transceiver that could accept supply voltages of 3V DC. Not exceeded with supply voltage higher then 3.1VDC because this is the higher voltage limit of module's inputs.

NOTE:
In this case Vin has to be set with a value compatible with the logic levels of the module. (Max 3.1V DC)

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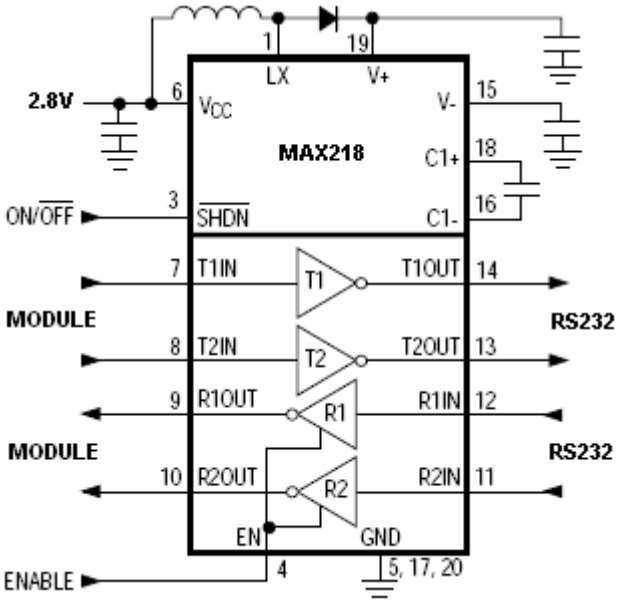
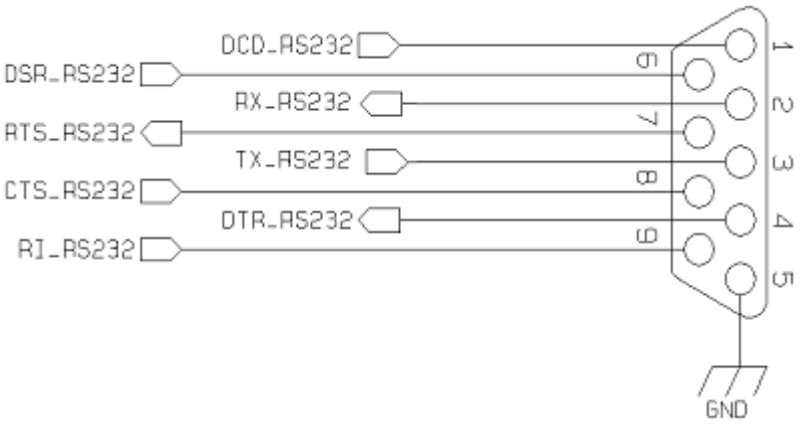
Second solution could be done using a MAXIM transceiver (MAX218) In this case the compliance with RS232 (+-5V) is possible.



Another level adapting method could be done using a standard RS232 Transceiver (MAX3237EAI) adding some resistors to adapt the levels on the GL868 Input lines.

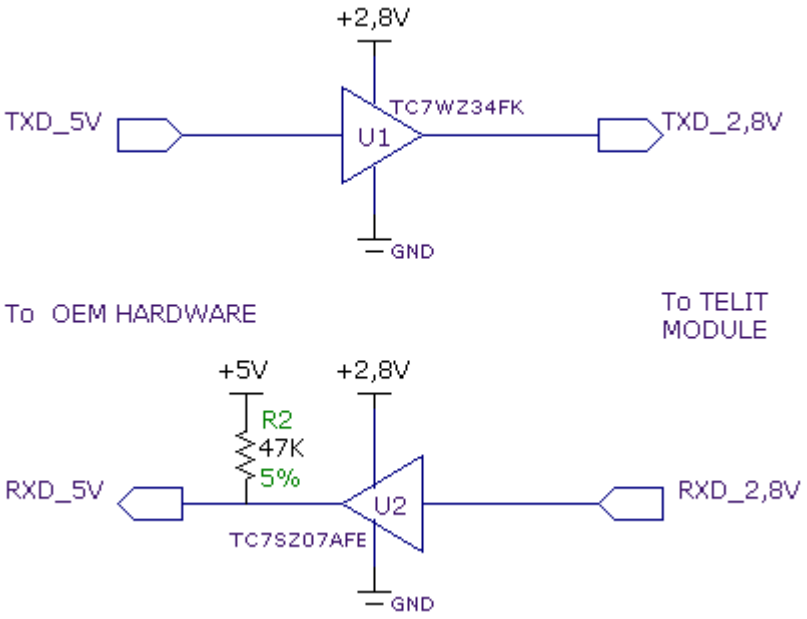
NOTE:
In this case has to be taken in account the length of the lines on the application to avoid problems in case of High-speed rates on RS232.

The RS232 serial port lines are usually connected to a DB9 connector with the following layout:



9.3. 5V UART level translation

If the OEM application uses a microcontroller with a serial port (UART) that works at a voltage different from 2.8 - 3V, then a circuitry has to be provided to adapt the different levels of the two set of signals. As for the RS232 translation there are a multitude of single chip translators. For example a possible translator circuit for a 5V TRANSMITTER/RECEIVER can be:



TIP:

Note that the TC7SZ07AE has open drain output; therefore the resistor R2 is mandatory.

NOTE:

The UART input line TXD (rx_uart) of the GL868 is NOT internally pulled up with a resistor, so there may be the need to place an external 47KΩ pull-up resistor, either the DTR (dtr_uart) and RTS (rts_uart) input lines are not pulled up internally, so an external pull-up resistor of 47KΩ may be required.

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NOTE:

The input lines working at 2.8VCMOS can be pulled-up with 47KΩ

In case of reprogramming of the module has to be considered the use of the RESET line to start correctly the activity.

The preferable configuration is having an external supply for the buffer.

NOTE:

In order to avoid a back powering effect it is recommended to avoid having any HIGH logic level signal applied to the digital pins of the GL868 when the module is powered OFF or during an ON/OFF transition.

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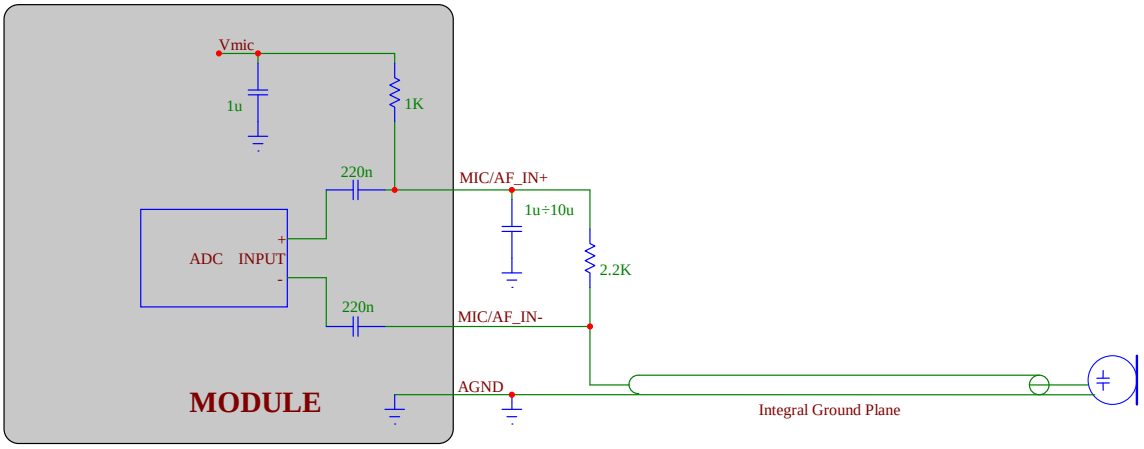
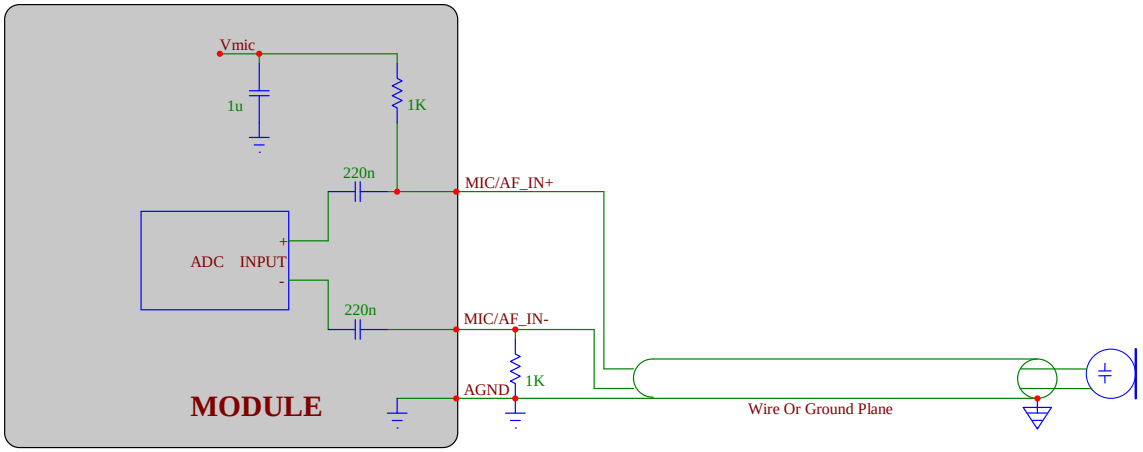
10. Audio Section Overview (not available on GL868-DUAL DATA ONLY version)

The Base Band Chip of the GL868 provides one input for audio to be transmitted (*Uplink*), that can be connected directly to a microphone or an audio source.
The bias for the microphone is already provided by the product; so the connection can be done in both following ways:

For more information refer to Telit document : " 80000NT10007a Audio Settings Application Note ".

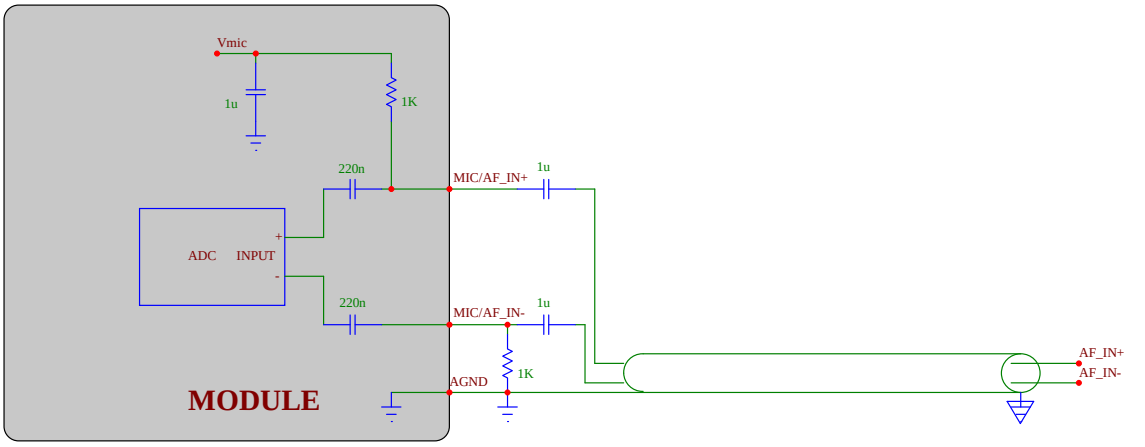
MIC connection

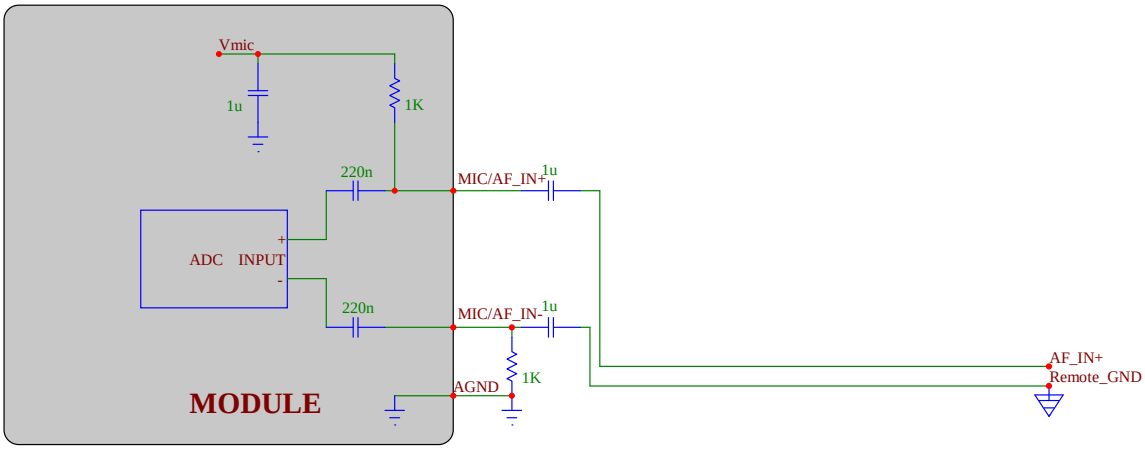




TIP:
Since the J-FET transistor inside the microphone acts as RF-detector-amplifier, ask vendor for a microphone with anti-EMI capacitor (usually a 33pF or a 10pF capacitor placed across the output terminals inside the case).

LINE-IN connection





If the audio source is not a mike but a different device, the following connections can be done.
Place a 1Kohm resistor to ground on the negative input, in order to get balanced the input; than connect the source via 1uF capacitor, so the DC current is blocked.
Since the input is differential, the common mode voltage noise between the two (different) ground is rejected, provided that both AF_IN+ & AF_IN- are connected directly onto the source.

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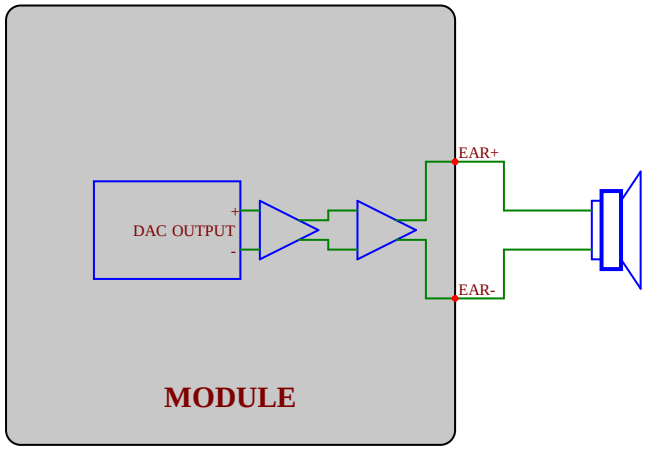
EAR connection connection



The audio output of the GL868 is balanced, this is helpful to double the level and to reject common mode (click and pop are common mode and therefore rejected).
These outputs can drive directly a small loudspeaker with electrical impedance not lower than 8Ohm.

TIP:
in order to get the maximum audio level at a given output voltage level (dBspl/Vrms), the following breaking through procedure can be used. Have the loudspeaker as close as you can to the listener (this simplify also the echo cancelling); choose the loudspeaker with the higher sensitivity (dBspl per W); choose loudspeakers with the impedance close to the limit (ex: 16 or 8 Ohm), in order to feed more power inside the transducer (it increases the W/Vrms ratio). If this were not enough, an external amplifier should be used.

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10.1. Electrical Characteristics

10.1.1. Input Lines

Microphone/Line-in path	
Line Type	Differential
Coupling capacitor	≥ 1µF
Differential input resistance	1kΩ/2kΩ/2.2kΩ
Levels	
To have 0dBm0 @1KHz *(*)*	Differential input voltage
AT#HFMICG=0	290mVrms
AT#HFMICG=1 (+6dB)	145mVrms
AT#HFMICG=2 (+12dB)	72mVrms
AT#HFMICG=3 (+18dB)	36mVrms
AT#HFMICG=4 (+24dB)	18mVrms
AT#HFMICG=5 (+30dB)	9mVrms
AT#HFMICG=6 (+36dB)	4.5mVrms
AT#HFMICG=7 (+42dB)	2.25mVrms

(*) 0 dBm0 in the network are -3.14 dBfs

TIP:
The Electrect microphone is internally amplified by a J-Fet transistor, thus the sound is carried out as saturation drain current; this means that the norton equivalence has to be considered. The signal is converted to voltage on the 2.2KOhm resistance, from there on circuitry has to be routed in order to not pick up common mode noise; beware of the return path (ground).

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10.1.2. Output Lines

EAR/Line-out Output	
Differential line coupling	Direct connection (V_{DC}=1.3÷1.6V)
Single-ended line coupling	One EAR terminal connected via a DC-block capacitor, the other one left open
output load resistance	≥ 8 Ω
internal output resistance	4 Ω (*typ.*)
signal bandwidth	250÷3400Hz *(@ -3dB with default filter)*
max. differential output voltage	1120mV$_{pp}$ *@3.14dBm0 (*)*
differential output voltage	550mV$_{rms}$ *@0dBm0 (*)*
volume increment	2dB per step
volume steps	0..10

(*) in default condition: AT+CLVL=10, AT#HFRECG=0

TIP :

We suggest driving the load differentially; this kills all the common mode noises (click and pop, for example), the output swing will double (+6dB) and the big output coupling capacitor will be avoided.

However if particular OEM application needs, also a Single Ended *(S.E)* circuitry can be implemented. The OEM circuitry shall be designed to reduce the common mode noise typically generated by the return path of the big currents.

In order to get the maximum power output from the device, the resistance of the tracks has to be negligible in comparison to the load.

WARNING.

When in *Single Ended* configuration, the unused output line must be left open: if this constraint is not respected, the output stage will be damaged.

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11. General Purpose I/O

The general purpose I/O pads can be configured to act in three different ways:

- input
- output
- alternate function (*internally controlled*)

Input pads can only be read; they report the digital value (high or low) present on the pad at the read time .
Output pads can only be written or queried and set the value of the pad output.
An alternate function pad is internally controlled by the GL868 firmware and acts depending on the function implemented.

For Logic levels please refer to chapter 8.

The following table shows the available GPIO on the GL868.

Pin	Signal	I/O	Function	Type	Input / output current	Default State	ON_OFF state	State during Reset	Note
42	GPIO_01	I/O	Configurable GPIO	CMOS 2.8V	1uA/1mA	INPUT	0	0	Alternate function DVI_WA0
41	GPIO_02	I/O	Configurable GPIO	CMOS 2.8V	1uA/1mA	INPUT	0	0	Alternate function JDR and DVI_RX
40	GPIO_03	I/O	Configurable GPIO	CMOS 2.8V	1uA/1mA	INPUT	0	0	Alternate function DVI_TX
39	GPIO_04	I/O	Configurable GPIO	CMOS 2.8V	1uA/1mA	INPUT	0	0	Alternate function TX disable and DVI_CLK
29	GPIO_05	I/O	Configurable GPIO	CMOS 2.8V	1uA/1mA	INPUT	0	0	Alternate function RFTXMON
28	GPIO_06	I/O	Configurable GPIO	CMOS 2.8V	1uA/1mA	INPUT	0	0	Alternate function ALARM
27	GPIO_07	I/O	Configurable GPIO	CMOS 2.8V	1uA/1mA	INPUT	0	0	Alternate function BUZZER
26	GPIO_08	I/O	Configurable GPIO	CMOS 2.8V	1uA/1mA	INPUT	0	0	Alternate function STAT_LED

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Also the UART ‘s control flow pins can be ubable as GPI/O.

Pin	Signal	I/O	Function	Type	Input / output current	Default State	ON_OFF state	State during Reset	Note
1	GPO_A	O	Configurable GPO	CMOS 2.8V	1uA/1mA	INPUT	0	0	Alternate function C109/DCD
2	GPO_B	O	Configurable GPO	CMOS 2.8V	1uA/1mA	INPUT	0	0	Alternate function C125/RING
3	GPO_C	O	Configurable GPO	CMOS 2.8V	1uA/1mA	INPUT	0	0	Alternate function C107/DSR
4	GPI_E	I	Configurable GPI	CMOS 2.8V	1uA/1mA	INPUT	0	0	Alternate function C108/DTR
5	GPI_F	I	Configurable GPI	CMOS 2.8V	1uA/1mA	INPUT	0	0	Alternate function C105/RTS
6	GPO_D	O	Configurable GPO	CMOS 2.8V	1uA/1mA	INPUT	0	0	Alternate function C106/CTS

11.1. GPIO Logic levels

Where not specifically stated, all the interface circuits work at 2.8V CMOS logic levels.
The following table shows the logic level specifications used in the GL868 interface circuits:

Absolute Maximum Ratings -Not Functional

Parameter	Min	Max
Input level on any digital pin when on (CMOS 2.8)	-0.3V	+3.1V
Input level on any digital pin when on (CMOS 1.8)	-0.3V	+2.1V
Input voltage on analog pins when on	-0.3V	+3.0V

Operating Range - Interface levels (2.8V CMOS)

Level	Min	Max
Input high level	2.1V	3.1V
Input low level	0V	0.5V
Output high level	2.2V	3.1V
Output low level	0V	0.35V

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11.2. Using a GPIO Pad as INPUT

The GPIO pads, when used as inputs, can be connected to a digital output of another device and report its status, provided this device has interface levels compatible with the 2.8V CMOS levels of the GPIO.
If the digital output of the device to be connected with the GPIO input pad has interface levels different from the 2.8V CMOS, then it can be buffered with an open collector transistor with a 47K pull up to 2.8V.

NOTE:

In order to avoid a back powering effect it is recommended to avoid having any HIGH logic level signal applied to the digital pins of the GL868 when the module is powered OFF or during an ON/OFF transition.

TIP:

The V_AUX / PWRMON pin can be used for input pull up reference or/and for ON/OFF monitoring.

11.3. Using a GPIO Pad as OUTPUT

The GPIO pads, when used as outputs, can drive 2.8V CMOS digital devices or compatible hardware. When set as outputs, the pads have a push-pull output and therefore the pull-up resistor may be omitted.

11.4. Using the RFTXMON Output GPIO5

The GPIO5 pin, when configured as RFTXMON Output, is controlled by the GL868 module and will rise when the transmitter is active and fall after the transmitter activity is completed.

There are 2 different modes for this function:

1) Active during all the Call:

For example, if a call is started, the line will be HIGH during all the conversation and it will be again LOW after hanged up.
The line rises up 300ms before first TX burst and will became again LOW from 500ms to 1s after last TX burst.

2) Active during all the TX activity:

The GPIO is following the TX bursts

Please refer to the AT User interface manual for additional information on how to enable this function.

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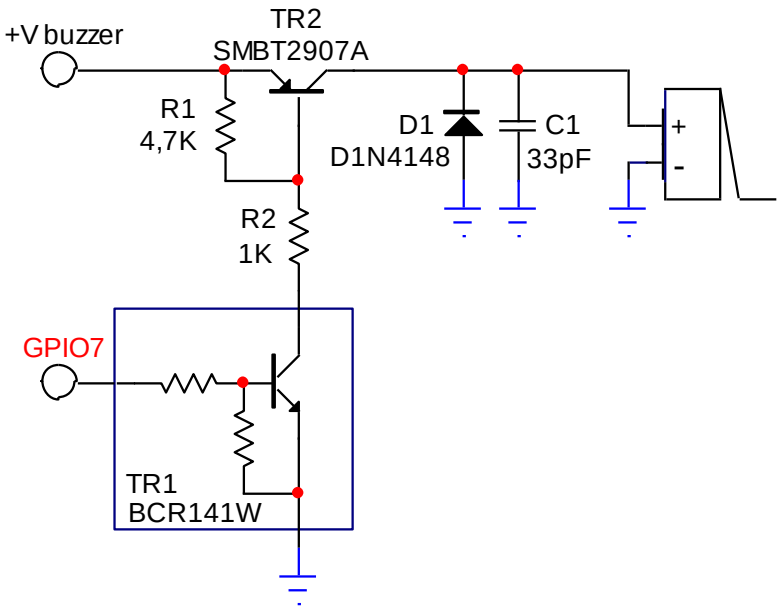
11.5. Using the Alarm Output GPIO6

The GPIO6 pad, when configured as Alarm Output, is controlled by the GL868 module and will rise when the alarm starts and fall after the issue of a dedicated AT command.
This output can be used to controlling microcontroller or application at the alarm time.

11.6. Using the Buzzer Output GPIO7

The GPIO7 pad, when configured as Buzzer Output, is controlled by the GL868 module and will drive a Buzzer driver with appropriate square waves.
This permits to your application to easily implement Buzzer feature with ringing tones or melody played at the call incoming, tone playing on SMS incoming or simply playing a tone or melody when needed.

A sample interface scheme is included below to give you an idea of how to interface a Buzzer to the GPIO7:



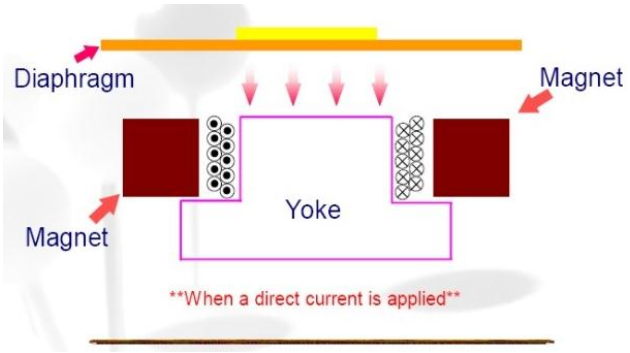
NOTE:

To correctly drive a buzzer a driver must be provided, its characteristics depend on the Buzzer and for them refer to your buzzer vendor**.**

11.7. Magnetic Buzzer Concepts

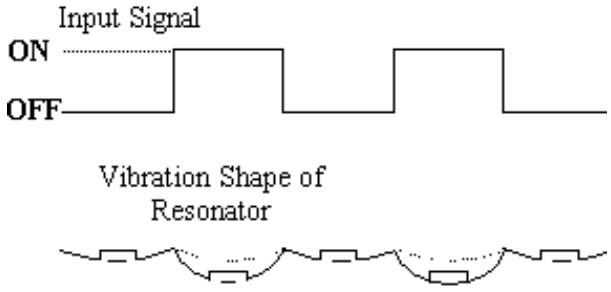
11.7.1. Short Description

A magnetic Buzzer is a sound-generating device with a coil located in the magnetic circuit consisting of a permanent magnet, an iron core, a high permeable metal disk and a vibrating diaphragm.



Drawing of the Magnetic Buzzer.

The disk and diaphragm are attracted to the core by the magnetic field. When an oscillating signal is moved through the coil, it produces a fluctuating magnetic field which vibrates the diaphragm at a frequency of the drive signal. Thus the sound is produced relative to the frequency applied.



Diaphragm movement.

11.7.2. Frequency Behavior

The frequency behaviour represents the effectiveness of the reproduction of the applied signals. Because performance is related to a square driving waveform (whose amplitude varies from 0V to V_{pp}), if you modify the waveform (*e.g. from square to sinus*) the frequency response will change.

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11.7.3. Power Supply Influence

Applying a signal whose amplitude is different from that suggested by the manufacturer, the performance change following the rule "if resonance frequency f_o increases, amplitude decreases".
Because resonance frequency depends on acoustic design, by lowering the amplitude of the driving signal the response bandwidth tends to become narrow, and vice versa.
Summarizing: $V_{pp} \uparrow \rightarrow f_o \downarrow$ $V_{pp} \downarrow \rightarrow f_o \uparrow$

The risk is that the f_o could easily fall outside of new bandwidth; consequently the SPL could be much lower than the expected.

WARNING:
It is very important to respect the sense of the applied voltage: never apply to the *"-" pin* a voltage more positive than the *"+" pin*: if this happens, the diaphragm vibrates in the opposite direction with a high probability to be expelled from its physical position. This damages the device permanently.

11.7.4. Working Current Influence

In the component data sheet you will find the value of MAX CURRENT: this represents the maximum average current that can flow at nominal voltage without current limitation. In other words it is not the peak current, which could be twice or three times higher. If driving circuitry does not support these peak values, the SPL will never reach the declared level or the oscillations will stop.

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11.8. STAT LED Indication of network service availability

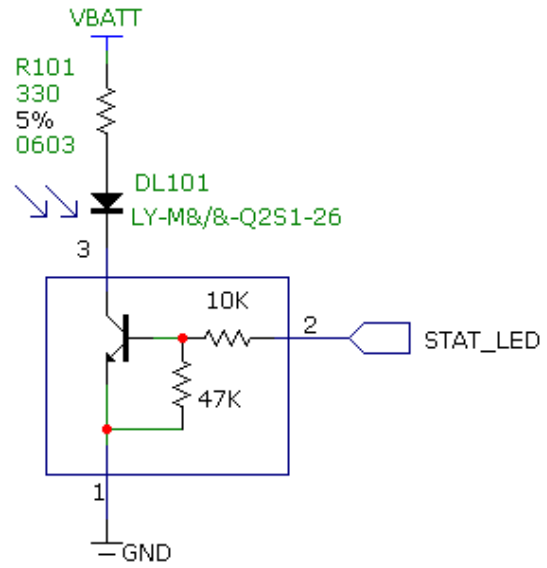
The STAT_LED pin status shows information on the network service availability and Call status. In the GL868 modules, the STAT_LED usually needs an external transistor to drive an external LED. Therefore, the status indicated in the following table is reversed with respect to the pin status. The AT command to enable the function is AT#SLED=2, in order to save the function use the AT command AT#SLEDSAV, the AT command AT#SLED=0 disable the function and the functionality of GPIO8 can be used. (see AT Command user guide)

LED status	Device Status
Permanently off	Device off
Fast blinking (Period 1s, Ton 0,5s)	Net search / Not registered / turning off
Slow blinking (Period 3s, Ton 0,3s)	Registered full service
Permanently on	a call is active

NOTE:

Don't use the STAT LED function if the GPIO 8 function is enabled and vice versa!

A schematic example could be:



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11.9. SIMIN detect function

All the GPIO pins can be used as SIM DETECT input. The AT Command used to enable the function is:

#SIMINCFG– SIMIN pin configuration	**SELINT 2**
AT#SIMINCFG = <GPIO_ pin>	The command enable the function on the general purpose I/O pin **GPIO<pin>** Parameters: **<GPIO_pin>** - GPIO pin number; supported range is from 1 to 8 (see chapter **Error! Reference source not found.**)
AT#SIMINCFG?	Read command reports the selected I/O pin in the format: **#SIMINCFG: 1**
AT#SIMINCFG =?	Test command reports supported range of values for parameters in the format: **#SIMINCFG : (0 – 8)** 0 = disabled

Use the AT command **AT#SIMDET=2** to enable the SIMIN detection
Use the AT command AT&W0 and AT&P0 to store the SIMIN detection in the common profile (See AT Command user guide)

NOTE:

Don’t use the SIM IN function on the same pin where the GPIO function is enabled and vice versa!

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11.10. RTC Bypass out

The VRTC pin brings out the Real Time Clock supply, which is separate from the rest of the digital part, allowing having only RTC going on when all the other parts of the device are off.
To this power output a backup battery can be added in order to increase the RTC autonomy during power off of the main battery (power supply). NO Devices must be powered from this pin.

11.11. SIM Holder Implementation

Please refer to the related User Guide (SIM Holder Design Guides, 80000NT10001a).

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12. DAC and ADC section

12.1. DAC Converter

12.1.1. Description

The GL868 provides a Digital to Analog Converter. The signal (named DAC_OUT) is available on pin **15** of the GL868.
The on board DAC is a 10 bit converter, able to generate a analogue value based a specific input in the range from 0 up to 1023. However, an external low-pass filter is necessary

	Min	Max	Units
Voltage range (filtered)	0	2,6	Volt
Range	0	1023	Steps

The precision is 10 bits so, if we consider that the maximum voltage is 2V, the integrated voltage could be calculated with the following formula:

Integrated output voltage = (2 *value) / 1023

DAC_OUT line must be integrated (for example with a low band pass filter) in order to obtain an analog voltage.

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12.1.2. Enabling DAC

An *AT command* is available to use the DAC function.
The command is: **AT#DAC= [**<*enable*> **[,** <*value*>**]]**

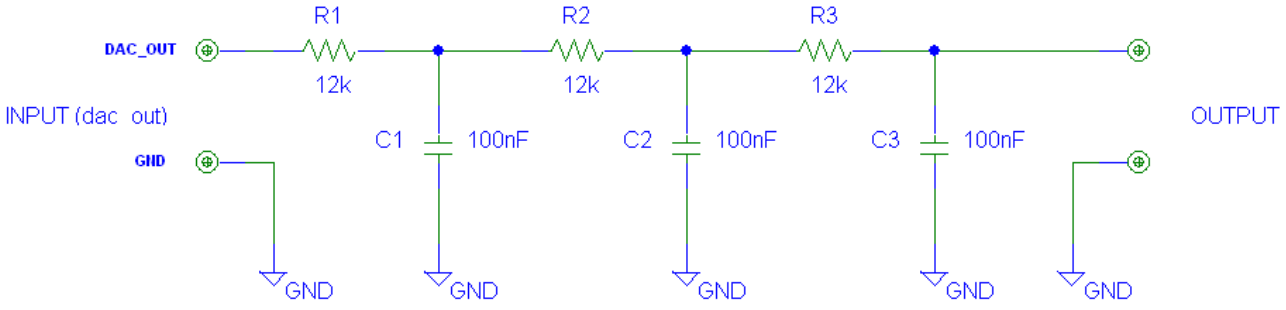
<*value*> - scale factor of the integrated output voltage (0..1023 - 10 bit precision)
it must be present if **<*enable*>*=1***

Refer to SW User Guide or AT Commands Reference Guide for the full description of this function.

NOTE:

The DAC frequency is selected internally. D/A converter must not be used during POWERSAVING.

12.1.3. Low Pass Filter Example



12.2. ADC Converter

12.2.1. Description

The on board A/D are 11-bit converter. They are able to read a voltage level in the range of 0÷2 volts applied on the ADC pin input, store and convert it into 11 bit word.

	Min	Max	Units
Input Voltage range	0	2	Volt
AD conversion	-	11	bits
Resolution	-	< 1	mV

The GL868 module provides 2 Analog to Digital Converters.
The input lines are:

ADC_IN1
available on pin 13

ADC_IN2
available on pin 14

12.2.2. Using ADC Converter

An AT command is available to use the ADC function.

The command is ***AT#ADC=1,2***

The read value is expressed in mV

Refer to SW User Guide or AT Commands Reference Guide for the full description of this function.

12.3. Debug of the GL868 in production

To test and debug the mounting of the GL868, we strongly recommend to foreseen test pads on the host PCB, in order to check the connection between the GL868 itself and the application and to test the performance of the module connecting it with an external computer. Depending by the customer application, these pads include, but are not limited to the following signals:

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pin	signal
38, 37	VBATT & VBATT_PA
32, 33, 35, 36, 46	GND
7	TXD
8	RXD
5	RTS
43	V_AUX / PWRMON
47	RESET*
45	TX_AUX
44	RX_AUX

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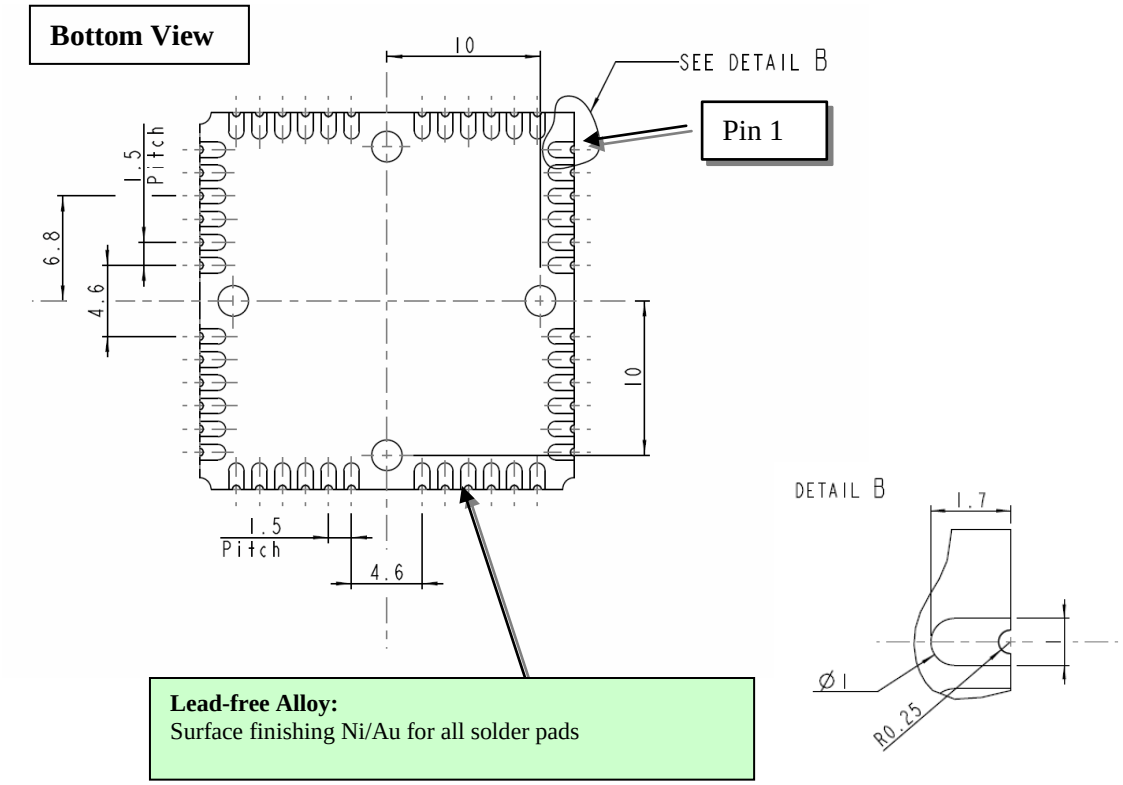
13. Mounting the GL868 on your Board

13.1. General

The GL868 modules have been designed in order to be compliant with a standard lead-free SMT process.

13.2. Module finishing & dimensions



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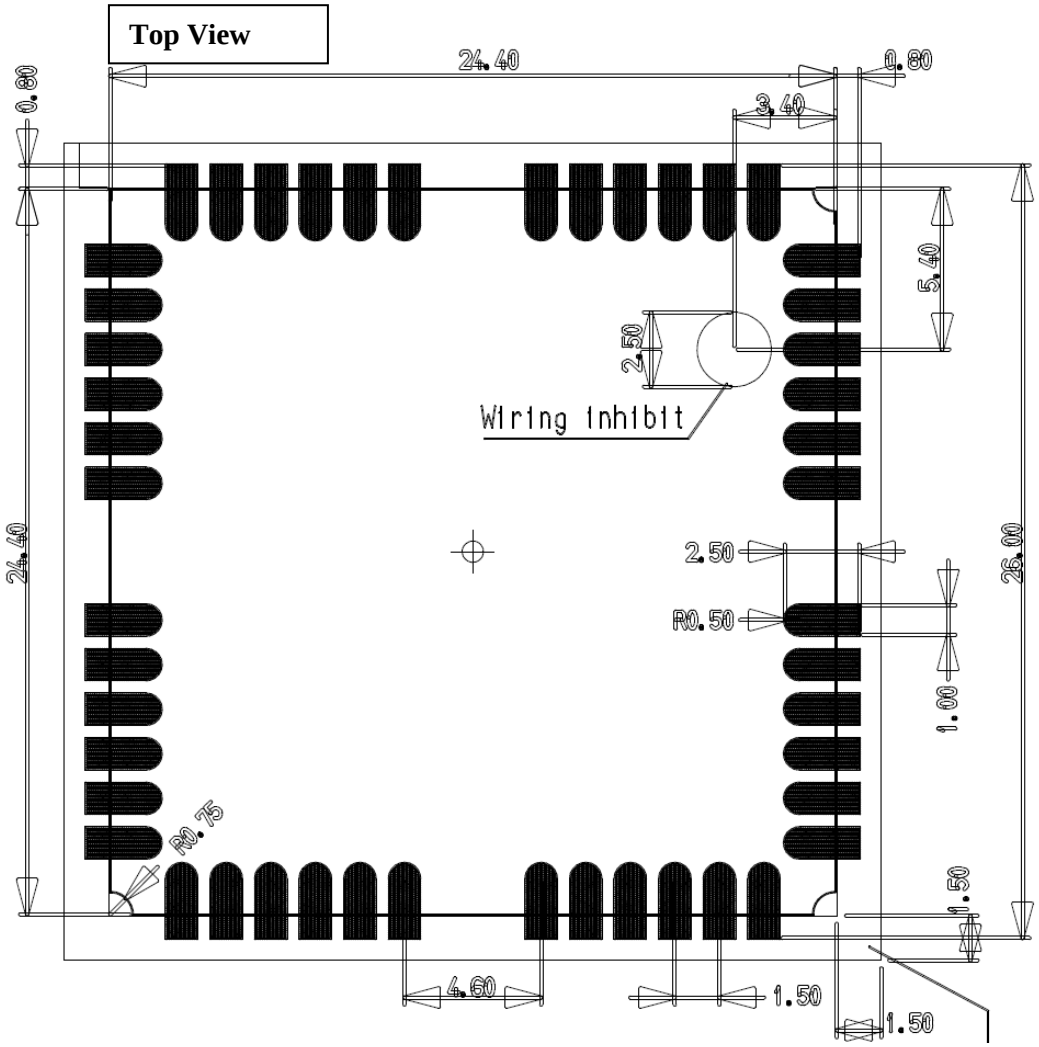
13.3. Recommended foot print for the application



In order to easily rework the GE868 is suggested to consider on the application a 1.5 mm placement inhibit area around the module.
It is also suggested, as common rule for an SMT component, to avoid having a mechanical part of the application in direct contact with the module.

NOTE:
In the customer application, the region under WIRING INHIBIT (see figure) must be clear from signal or ground paths.

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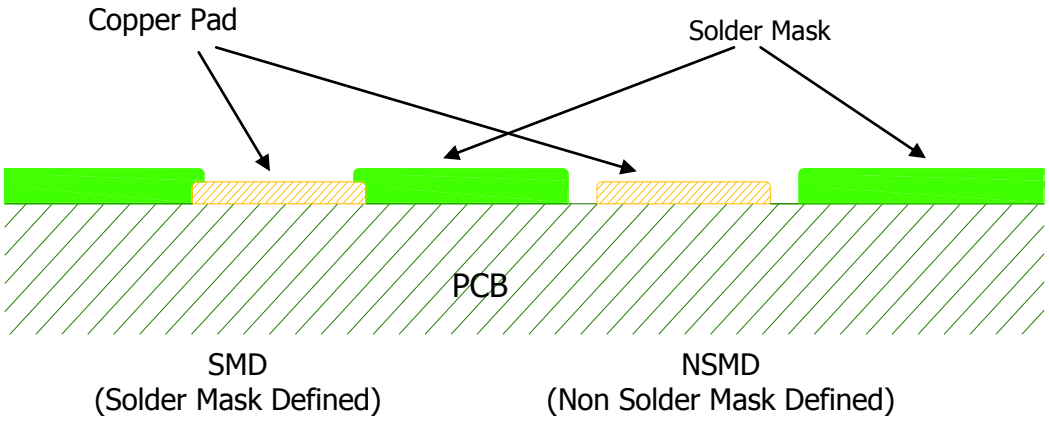
13.4. Stencil

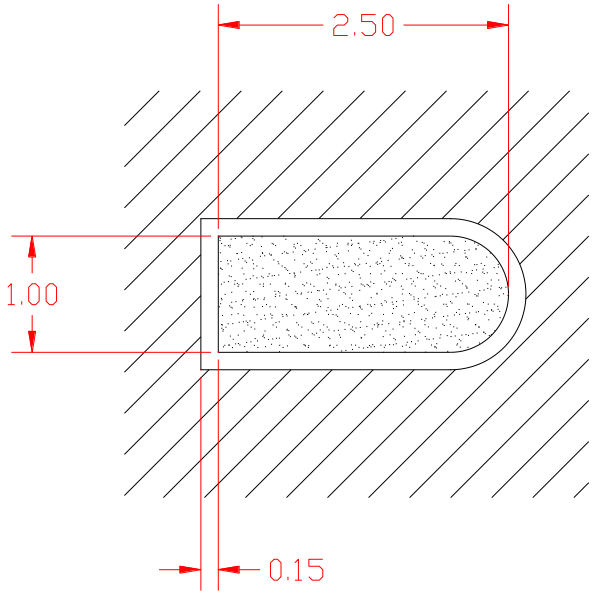
Stencil's apertures layout can be the same of the recommended footprint (1:1), we suggest a thickness of stencil foil ≥ 120µm.

13.5. PCB pad design

Non solder mask defined (NSMD) type is recommended for the solder pads on the PCB.



13.6. Recommendations for PCB pad dimensions (mm)



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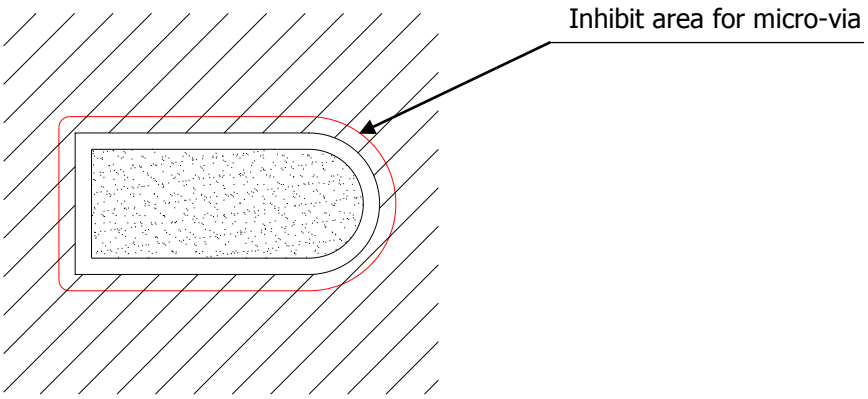
It is not recommended to place via or micro-via not covered by solder resist in an area of 0,3 mm around the pads unless it carries the same signal of the pad itself (see following figure).



Holes in pad are allowed only for blind holes and not for through holes.

Recommendations for PCB pad surfaces:

Finish	Layer thickness [µm]	Properties
Electro-less Ni / Immersion Au	3 –7 / 0.05 – 0.15	good solder ability protection, high shear force values

The PCB must be able to resist the higher temperatures which are occurring at the lead-free process. This issue should be discussed with the PCB-supplier. Generally, the wettability of tin-lead solder paste on the described surface plating is better compared to lead-free solder paste.
It is not necessary to panel the application PCB, however in that case it is suggested to use milled contours and predrilled board breakouts; scoring or v-cut solutions are not recommended.

13.7. Solder paste

	Lead free
Solder paste	Sn/Ag/Cu

We recommend to use only “no clean” solder paste in order to avoid the cleaning of the modules after assembly.

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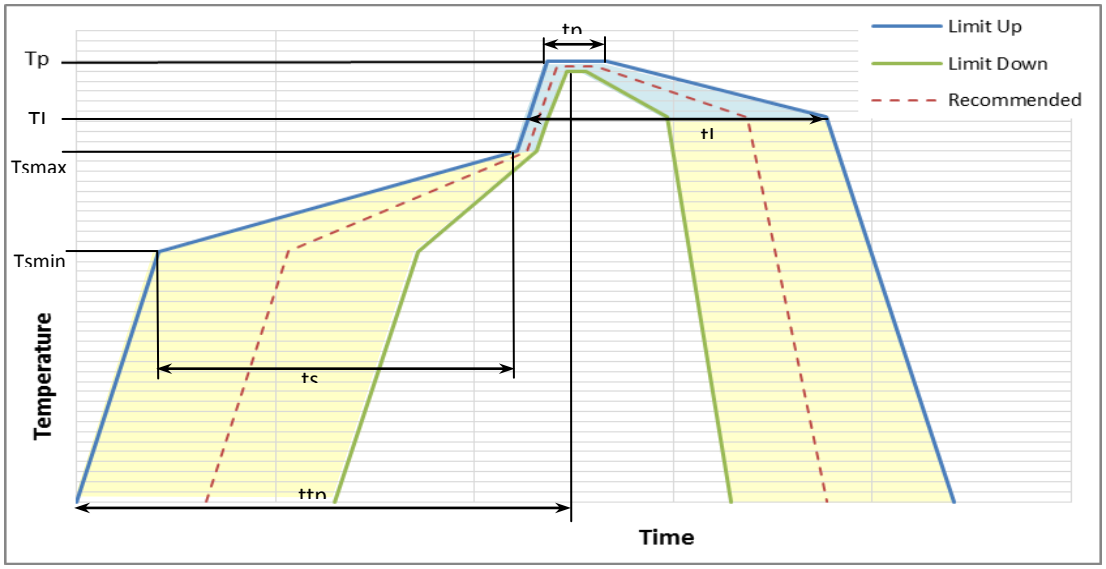
13.7.1. GL868 Solder reflow

Recommended solder reflow profile



Profile Feature	Pb-Free Assembly
Average ramp-up rate (TL to TP)	3°C/second max
Preheat – Temperature Min (Tsmin) – Temperature Max (Tsmax) – Time (min to max) (ts)	 150°C 200°C 60-180 seconds
Tsmax to TL – Ramp-up Rate	 3°C/second max
Time maintained above: – Temperature (TL) – Time (tL)	 217°C 60-150 seconds
Peak Temperature (Tp)	245 +0/-5°C
Time within 5°C of actual Peak Temperature (tp)	10-30 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature (ttp)	8 minutes max.

NOTE:

All temperatures refer to topside of the package, measured on the package body surface

WARNING:

The GL868 module withstands one reflow process only.

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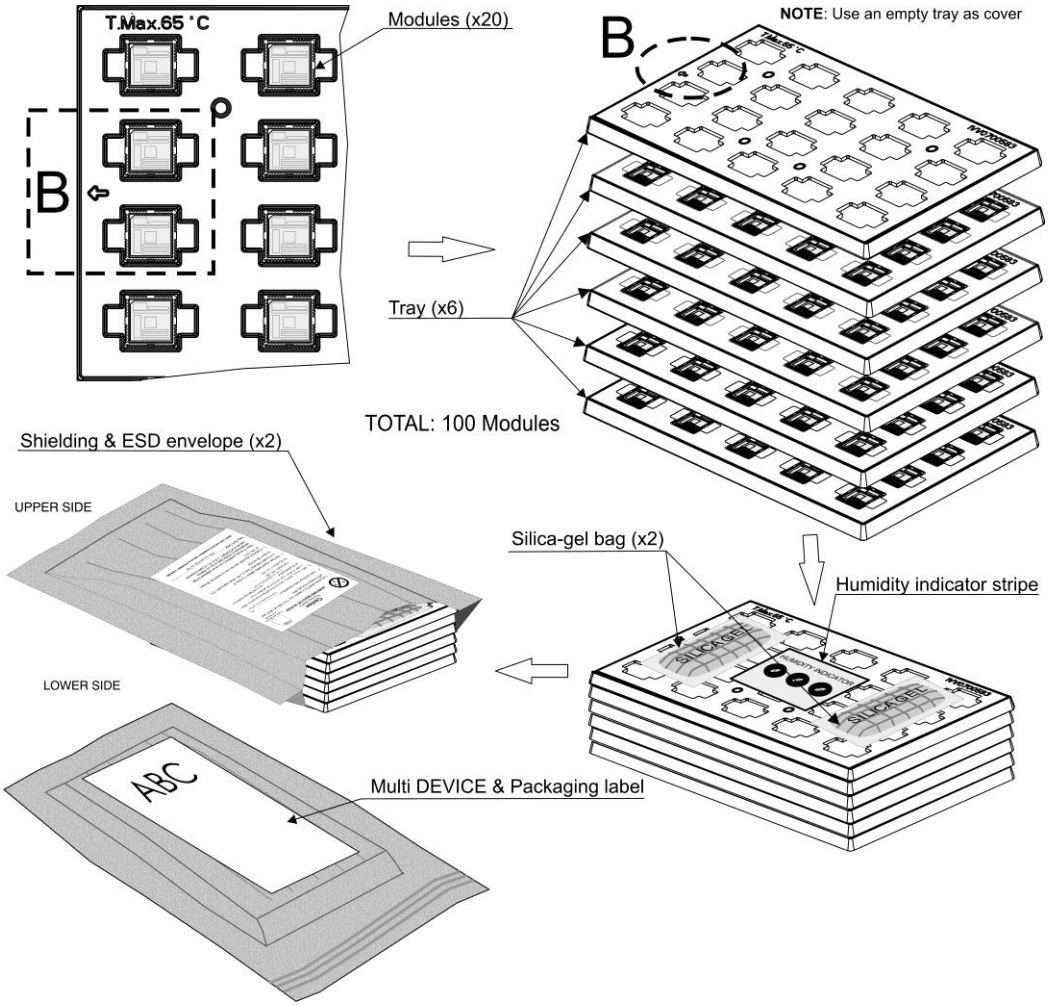
14. Packing system

The GL868 modules are packaged on trays of ***20*** pieces each. This is especially suitable for the GL868 according to SMT processes for pick & place movement requirements.



NOTE:

All temperatures refer to topside of the package, measured on the package body surface

WARNING:

These trays can withstand at the maximum temperature of 65° C.

14.1. Moisture sensibility

The level of moisture sensibility of GL868 is “3”, in according with standard IPC/JEDEC J-STD-020, take care all the relatives requirements for using this kind of components.
Calculated shelf life in sealed bag: 4 months at <40°C and <90% relative humidity (RH).

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15. Conformity Assessment Issues

The Telit **GL868 Module** has been assessed in order to satisfy the essential requirements of the R&TTE Directive 1999/05/EC (Radio Equipment & Telecommunications Terminal Equipments) to demonstrate the conformity against the harmonised standards with the final involvement of a Notified Body.

If the module is installed in conformance to the Telit installation manuals, no further evaluation under **Article 3.2** of the R&TTE Directive and do not require further involvement of a R&TTE Directive Notified Body for the final product.

In all other cases, or if the manufacturer of the final product is in doubt, then the equipment integrating the radio module must be assessed against **Article 3.2** of the R&TTE Directive.

In all cases the assessment of the final product must be made against the Essential requirements of the R&TTE Directive **Articles 3.1(a)** and **(b)**, Safety and EMC respectively, and any relevant Article 3.3 requirements.

This Hardware User Guide contains all the information you may need for developing a product meeting the R&TTE Directive.

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16. SAFETY RECOMMANDATIONS

READ CAREFULLY

Be sure the use of this product is allowed in the country and in the environment required. The use of this product may be dangerous and has to be avoided in the following areas:

- Where it can interfere with other electronic devices in environments such as hospitals, airports, aircrafts, etc
- Where there is risk of explosion such as gasoline stations, oil refineries, etc

It is responsibility of the user to enforce the country regulation and the specific environment regulation.

Do not disassemble the product; any mark of tampering will compromise the warranty validity.

We recommend following the instructions of the hardware user guides for a correct wiring of the product. The product has to be supplied with a stabilized voltage source and the wiring has to be conforming to the security and fire prevention regulations.

The product has to be handled with care, avoiding any contact with the pins because electrostatic discharges may damage the product itself. Same cautions have to be taken for the SIM, checking carefully the instruction for its use. Do not insert or remove the SIM when the product is in power saving mode.

The system integrator is responsible of the functioning of the final product; therefore, care has to be taken to the external components of the module, as well as of any project or installation issue, because the risk of disturbing the GSM network or external devices or having impact on the security. Should there be any doubt, please refer to the technical documentation and the regulations in force.

Every module has to be equipped with a proper antenna with specific characteristics. The antenna has to be installed with care in order to avoid any interference with other electronic devices and has to guarantee a minimum distance from the body (20 cm). In case of this requirement cannot be satisfied, the system integrator has to assess the final product against the SAR regulation.

The European Community provides some Directives for the electronic equipments introduced on the market. All the relevant information's are available on the European Community website:

http://ec.europa.eu/enterprise/sectors/rtte/documents/

The text of the Directive 99/05 regarding telecommunication equipments is available, while the applicable Directives (Low Voltage and EMC) are available at:

http://ec.europa.eu/enterprise/sectors/electrical

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17. Document History

Revision	Date	Changes
ISSUE#0	2010-09-30	First ISSUE
Rev.1	2010-11-11	Chapt. 5.3.1 Removed statement related ON* pad.
Rev.2	2010-11-23	Chapt. 4.1 Pin Out- change definition on pin 39 and 26; Chapt. 11 General Purpose I/O Pin 39 Chapt. 11.8 STAT LED Indication of network service availability – AT Command reference Chapt. 11.9 SIMIN Detect function AT Command reference Chapt. 13.14 Solder paste – recommended “no clean” solder paste
Rev. 3	2011-03-10	VBATT_PA power consumption specification Page 18 typical 2uA max 20uA Page 23 typical 2uA max 20uA AUX serial port naming from RXD_AUX; TXD_AUX to RX_AUX; TX_AUX
Rev. 4	2011-05-25	Added GL868-DUAL Data Only to applicability table Added note on table in par 4.1 and on chapter 10
Rev.5	2012-06-06	Added chapter 13 assembly Added chapters 6.2 (power consumption) 6..2.1 (power cons. plots)

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